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This index covers all items—papers, correspondence, reviews, etc.—that appeared in this periodical during 1984, and items from prior years that were commented upon or corrected in 1984. The index is divided into an Author Index and a Subject Index, both arranged alphabetically.

The *Author Index* contains the primary entry for each item; this entry is listed under the name of the first author and includes coauthor names, title, location of the item, and notice of corrections and comments if any. Cross-references are given from each coauthor name to the name of the corresponding first author. The location of the item is specified by the journal name (abbreviated), year, month, and inclusive pages.

The *Subject Index* contains several entries for each item, each consisting of a subject heading, modifying phrase(s), first author's name—followed by + if the paper has coauthors—and enough information to locate the item. For coauthors, title, comments, and corrections if any, etc., it is necessary to refer to the primary entry in the Author Index. Subject cross-references are provided as required by the subject matter. Also provided whenever appropriate are listings under generic headings such as *Bibliographies* (for any paper with at least 50 references, as well as papers that are exclusively bibliographies), *Book reviews*, and *Special issues*.

AUTHOR INDEX

A

- Abbas, C. Christiaan.** A theoretical explanation of the carrier lifetime as a function of the injection level in gold-doped silicon; *T-ED Oct 84* 1428–1432
- Abdeshaah, Rahim**, and K. L. Wang. Transport study in Si – silicide – Si transistors using a Monte Carlo technique; *T-ED Dec 84* 1701–1708
- Abrokwah, J. K.**, see Cirillo, N. C., Jr.; *T-ED Dec 84* 1963
- Adler, Michael S.**, see Possin, George E.; *T-ED Jan 84* 3–17
- Adler, Michael S.**, see Love, Robert P.; *T-ED Jun 84* 817–820
- Adler, Michael S.**, see Baliga, B. Jayant; *T-ED Jun 84* 821–828
- Adler, Michael S.**, King W. Owyang, B. Jayant Baliga, and Richard A. Kokosa. The evolution of power device technology; *T-ED Nov 84* 1570–1591
- Ahmad, S.**, see Akhtar, J.; *T-ED Dec 84* 1781–1783
- Ahmed, S. S.**, see Kim, Dae M.; *T-ED Apr 84* 480–493
- Ahmed, S. S.**, see Khondker, A. N.; *T-ED Apr 84* 493–500
- Ahn, Saeyoung**, see Ganguly, Achintya K.; *T-ED Apr 84* 474–480
- Aida, Toshiyuki**, see Taguchi, Sadanori; *T-ED Jul 84* 900–903
- Aiken, W. Ross.** History of the Kaiser – Aiken thin cathode ray tube; *T-ED Nov 84* 1605–1608
- Aina, O. A.**, see Pande, K. P.; *T-ED Apr 84* 506–508
- Akanuma, O.**, see Nakayama, Y.; *T-ED Dec 84* 1987–1988
- Akers, Lex A.**, see Reasoner, Kelly J.; *T-ED Feb 84* 157–159
- Akers, Lex A.**, see Sugino, Michael; *T-ED Dec 84* 1823–1829
- Akhtar, J.**, and S. Ahmad. Breakdown voltage of a rectangular planar diffused junction with rounded corners; *T-ED Dec 84* 1781–1783
- Akiyama, Ikuo**, see Ishihara, Yasuo; *T-ED Jan 84* 83–88
- Akiyama, M.**, see Ishida, T.; *T-ED Dec 84* 1988
- Alavi, K.**, see Capasso, F.; *T-ED Dec 84* 1972–1973
- Amemiya, Yoshihito**, see Murase, Katsumi; *T-ED Dec 84* 1980–1981
- Amemiya, Yoshihito**, and Yoshihiko Mizushima. Bipolar-mode Schottky contact and applications to high-speed diodes; *T-ED Jan 84* 35–42
- Amrany, Daniel**, see Eitan, Boaz; *T-ED Jul 84* 934–942
- Anagnostopoulos, Constantine N.**, *Guest Ed.*, and Savvas G. Chamberlain, *Guest Ed.* Foreword to special issue; *T-ED Feb 84* 137–138
- Anagnostopoulos, Constantine N.**, Edward T. Nelson, James P. Lavine, Kwok Y. Wong, and David N. Nichols. Latch-up and image crossstalk suppression by internal gettering; *T-ED Feb 84* 225–231
- Anderson, R. J.**, see Asbeck, P. M.; *T-ED Dec 84* 1979
- Anderson, W. A.**, see Thayer, M.; *T-ED May 84* 619–621
- Andor, L.**, see Baltes, Henry P.; *T-ED Jul 84* 996–999
- Andrade, Thomas**, see Kennan, Wayne; *T-ED Dec 84* 1926–1930
- Andrade, Thomas**, see Moghe, Sanjay B.; *T-ED Dec 84* 1931–1937
- Anthony, Thomas C.**, see Bube, Richard H.; *T-ED May 84* 528–538
- Antoniadis, D.**, see Rodder, M.; *T-ED Dec 84* 1982–1983
- Antoniadis, Dimitri A.** Calculation of threshold voltage in nonuniformly doped MOSFET's; *T-ED Mar 84* 303–307
- Aoki, Kyoji**, see Iwai, Hiroshi; *T-ED Sep 84* 1149–1151
- Aoki, Yukio**, Toru Toyabe, Shojiro Asai, and Takaaki Hagiwara. CASTAM: A process variation analysis simulator for MOS LSI's; *T-ED Oct 84* 1462–1467

- Arai, Kouichi**, *see* Teranishi, Nobukazu; *T-ED Dec 84* 1829–1833
- Arienzo, Maurizio**, *see* Chuang, C. T.; *T-ED Oct 84* 1482–1486
- Armgarth, Marten**, *see* Dobos, Karoly; *T-ED Apr 84* 508–510
- Arnaud, Thierry**, *see* Chilo, Jean; *T-ED Mar 84* 347–352
- Arndt, R. A.**, *see* Meulenbergh, A.; *T-ED May 84* 720–721
- Arnold, D.**, *see* Fischer, Russell J.; *T-ED Dec 84* 1963–1964
- Arnold, Douglas J.**, *see* Drummond, Timothy J.; *T-ED Sep 84* 1164–1168
- Arnold, Douglas J.**, Russell J. Fischer, William F. Kopp, Timothy S. Henderson, and Hadis Morkoc. Microwave characterization of (Al,Ga)As/GaAs modulation-doped FET's: Bias dependence of small-signal parameters; *T-ED Oct 84* 1399–1402
- Arora, Narain D.**, and John R. Hauser. Spectral response of n+-n-p and n+-p photodiodes; *T-ED Apr 84* 430–434
- Asai, Shojiro**, *see* Sunami, Hideo; *T-ED Jun 84* 746–753
- Asai, Shojiro**, *see* Aoki, Yukio; *T-ED Oct 84* 1462–1467
- Asbeck, P. M.**, D. L. Miller, R. J. Anderson, and F. H. Eisen. GaAs/(Ga,Al)As heterojunction bipolar transistors with buried oxygen-implanted isolation layers (Abstr.); *T-ED Dec 84* 1979
- Asbeck, Peter M.**, Chien-Ping Lee, and Mau-Chung F. Chang. Piezoelectric effects in GaAs FET's and their role in orientation-dependent device characteristics; *T-ED Oct 84* 1377–1380
- Ashburn, Peter**, and B. Soerowirdjo. Comparison of experimental and theoretical results on polysilicon emitter bipolar transistors; *T-ED Jul 84* 853–860
- Atoda, N.**, *see* Matsumoto, K.; *T-ED Dec 84* 1987
- Awaji, Noriyuki**, *see* Uchiike, Heiju; *T-ED Jul 84* 943–950
- Awane, Katsunobu**, *see* Watanabe, Takashi; *T-ED Feb 84* 183–188
- Awano, Yuji**, Kazutaka Tomizawa, and Nobuo Hashizume. Principles of operation of short-channel gallium arsenide field-effect transistor determined by Monte Carlo method; *T-ED Apr 84* 448–452
- Ayasli, Yalcin**, *see* Weiler, Margaret H.; *T-ED Dec 84* 1854–1861
- Ayasli, Yalcin**, Stephen W. Miller, Robert Mozzi, and Larry K. Hanes. Capacitively coupled traveling-wave power amplifier; *T-ED Dec 84* 1937–1942
- Ayasli, Yalcin**, Stephen W. Miller, Robert Mozzi, and Larry K. Hanes. Wide-band monolithic phase shifter; *T-ED Dec 84* 1943–1947
- B**
- Baba, T.**, T. Mizutani, M. Ogawa, and D. Ohata. High performance (AlAs/n-GaAs superlattice)/GaAs 2DEGFET's with stabilized threshold voltage (Abstr.); *T-ED Dec 84* 1962
- Baccarani, Giorgio**, Matthew R. Wordeman, and Robert H. Dennard. Generalized scaling theory and its application to a 1/4 micrometer MOSFET design; *T-ED Apr 84* 452–462
- Baird, J. Mark**, *see* Lau, Y. Y.; *T-ED Mar 84* 337 (347)
- Baldwin, K.**, *see* Kiehl, R. A.; *T-ED Dec 84* 1968
- Baliga, B. Jayant**, *see* Possin, George E.; *T-ED Jan 84* 3–17
- Baliga, B. Jayant**, Michael S. Adler, Robert P. Love, Peter V. Gray, and Nathan D. Zommer. The insulated gate transistor: A new three-terminal MOS-controlled bipolar power device; *T-ED Jun 84* 821–828
- Baliga, B. Jayant**, *see* Adler, Michael S.; *T-ED Nov 84* 1570–1591
- Baliga, B. Jayant**. Switching speed enhancement in insulated gate transistors by electron irradiation; *T-ED Dec 84* 1790–1795
- Baltes, Henry P.**, *see* Popović, Radivoje S.; *T-ED Mar 84* 286–291
- Baltes, Henry P.**, L. Andor, A. Nathan, and H. G. Schmidt-Weinmar. Two-dimensional numerical analysis of a silicon magnetic field sensor (Brief); *T-ED Jul 84* 996–999
- Banerjee, S. K.**, M. Elahy, H. Shichijo, G. P. Pollack, W. F. Richardson, S. D. S. Malhi, A. H. Shah, P. K. Chatterjee, H. W. Lam, and R. H. Womack. Comparison of accumulation and inversion mode LPCVD polysilicon MOSFET characteristics for memory applications (Abstr.); *T-ED Dec 84* 1983
- Barbee, Troy**, *see* Gardner, Don; *T-ED Dec 84* 1965
- Barker, Richard Clark**, *see* Fossum, Eric R.; *T-ED Sep 84* 1168–1174
- Barker, Richard Clark**, *see* Fossum, Eric R.; *T-ED Dec 84* 1784–1789
- Barnes, P. A.**, *see* Koszi, L. A.; *T-ED Dec 84* 1910–1912
- Barnett, Allen M.**, *see* Parekh, Rajul H.; *T-ED May 84* 689–695
- Barnett, Larry R.**, *see* Lau, Y. Y.; *T-ED Mar 84* 337 (347)
- Baumert, Robert J.**, Leon E. Cameron, and Ralph A. Wilson, III. A mixed EFL I²L digital telecommunication integrated circuit; *T-ED Feb 84* 160–165
- Bayer, Paul W.**, *see* Levenson, Marc D.; *T-ED Jun 84* 753–763
- Bean, John C.**, *see* Luryi, Serge; *T-ED Sep 84* 1135–1139
- Beck, William A.**, and Norman E. Byer. Calculation of tunneling currents in (Hg,Cd)Te photodiodes using a two-sided junction potential; *T-ED Mar 84* 292–297

- Beckwith, Sharleen K.**, see Swanson, Richard M., *T-ED May 84* 661–654
- Beltrán, Nicolas**, see Groeseneken, Guido, *T-ED Jan 84* 42–53
- Bencuya, Selim S.**, and Andrew J. Steckl. Charge-packet splitting in charge-domain devices; *T-ED Oct 84* 1494–1501
- Besomi, P. R.**, see Schwartz, B., *T-ED Jun 84* 841–843
- Bhattacharyya, Arundhati, A.** Ghosal, and D. Chattopadhyay. Temperature dependence of peak drift velocity and threshold field in n-In_{0.53}Ga_{0.47}As (Brief); *T-ED Dec 84* 1918–1919
- Bhaumik, Basabi**, see Madan, Sudhir K., *T-ED Oct 84* 1509–1511
- Blakers, Andrew W.**, see Green, Martin A., *T-ED May 84* 679–683
- Blakey, Peter A.**, see Grondin, R. O., *T-ED Jan 84* 21–28
- Board, Kenneth, David J. Byrne**, and Malcolm S. Towers. The optimisation of on-resistance in vertical DMOS power devices with linear and hexagonal surface geometries; *T-ED Jan 84* 75–80
- Board, Kenneth**, see Darwish, Mohamed N., *T-ED Dec 84* 1769–1773
- Böhm, Markus**, Hella C. Scheer, and Hans-Günther Wagenmann. Nonequilibrium behavior of depletion, inversion, and accumulation grain boundaries; *T-ED Oct 84* 1440–1446
- Booth, Richard V. H.**, and M. H. White. An experimental method for the determination of the saturation point of a MOSFET; *T-ED Feb 84* 247–251
- Bosman, G.**, see van der Ziel, Alder, *T-ED Sep 84* 1280–1283
- Bozler, Carl O.**, see Zhu, Xichen C., *T-ED Oct 84* 1408–1413
- Bozler, Carl O.**, see Nichols, Kirby B., *T-ED Dec 84* 1969–1970
- Brault, Roberg G.**, see Kubena, Randall L., *T-ED Sep 84* 1186–1189
- Braun, Chris**, see Guha, Shekhar, *T-ED Jul 84* 992–993
- Brieger, K.-P.**, Willi Gerlach, and Joachim Pelka. The influence of surface charge and bevel angle on the blocking behavior of a high-voltage p⁺-n-n⁺ device; *T-ED Jun 84* 733–738
- Brockhoff, W.**, see Daembkes, Heinrich, *T-ED Aug 84* 1032–1037
- Brodersen, Robert W.**, see Liang, Mong-Song, *T-ED Sep 84* 1238–1244
- Brody, T. Peter**. The thin film transistor—A late flowering bloom; *T-ED Nov 84* 1614–1628
- Brooks, Bonnie G.**, see Tiedje, Tom, *T-ED May 84* 711–716
- Brors, D. L.**, see Monnig, K. A., *T-ED Dec 84* 1965–1966
- Brown, J. M.**, see Epler, J. E., *T-ED Dec 84* 1974–1975
- Brown, James C., Jr.**, see Vu, Tho T., *T-ED Feb 84* 144–156
- Brown, William C.** The microwave magnetron and its derivatives; *T-ED Nov 84* 1595–1605
- Bryan, R. P.**, see Hunter, A. T., *T-ED Dec 84* 1987
- Bube, Richard H.**, Alan L. Fahrenbruch, Robert Sinclair, Thomas C. Anthony, Charles Fortmann, Walter Huber, Chun-Teh Lee, Thomas Thorpe, and Tsutomu Yamashita. Cadmium telluride films and solar cells; *T-ED May 84* 528–538
- Bujatti, Marina**, see Miller, Daniel, *T-ED Dec 84* 1985–1986
- Bujatti, Marina**, see Wang, Faa-Ching, *T-ED Dec 84* 1986–1987
- Buonomo, Antonio**, and Carlo Di Bello. Nonlinear two-dimensional impurity diffusion in semiconductors: A quasi-linear numerical analysis; *T-ED Dec 84* 1708–1713
- Burkey, Bruce C.**, Gerrit Lubberts, Eugene A. Trabka, and Timothy J. Tredwell. Channel potential and channel width in narrow buried-channel MOSFETs; *T-ED Apr 84* 423–429
- Burnham, R. W.**, see Epler, J. E., *T-ED Dec 84* 1974–1975
- Burrows, Ian L. C.**, see Rys, Andrzej, *T-ED Apr 84* 500–505
- Burrus, C. A.**, see Lee, T. P., *T-ED Dec 84* 1974
- Byer, Norman E.**, see Beck, William A., *T-ED Mar 84* 292–297
- Byrne, David J.**, see Board, Kenneth, *T-ED Jan 84* 75–80
- C
- Caine, E. J.**, S. Subbanna, H. Kroemer, J. L. Merz, and A. Y. Cho. Staggered-lineup heterojunctions as sources of tunable below-gap radiation: Experimental verification (Abstr.); *T-ED Dec 84* 1914
- Caldwell, P. J.**, see Laidig, W. D., *T-ED Dec 84* 1975
- Cameron, Leon E.**, see Baumert, Robert J., *T-ED Feb 84* 160–165
- Campbell, Stephen A.**, see Preckshot, Nancy E., *T-ED Feb 84* 215–225
- Canfield, P.**, see Forbes, L., *T-ED Dec 84* 1986
- Capasso, F.**, K. Alavi, A. Y. Cho, J. M. Parsey, and B. Kasper. New low dark current high-speed Al_{0.48}In_{0.52}As/Ga_{0.47}In_{0.53}As avalanche photodiode by molecular-beam epitaxy for long wavelength fiber optic communication systems (Abstr.); *T-ED Dec 84* 1972–1973
- Cappy, A.**, see Daembkes, Heinrich, *T-ED Aug 84* 1032–1037
- Card, Howard C.**, see Mbewe, Dominic Jacob, *T-ED May 84* 523–527
- Card, Howard C.**, see De Groot, A. W., *T-ED Oct 84* 1365–1369
- Card, Howard C.**, see De Groot, A. W., *T-ED Oct 84* 1370–1376
- Cardi, E. A.**, see Cheng, C. L., *T-ED Dec 84* 1985
- Carter, David L.**, *Ed.* Change in editorial board; *T-ED May 84* 521
- Carter, David L.**, *Ed.* Foreword to Centennial special issue; *T-ED Nov 84* 1521
- Casey, H. Craig, Jr.**, *Guest Ed.* Foreword to special section; *T-ED Nov 84* 1629
- Cassard, Janet M.** A sensitivity analysis of SPICE parameters using an eleven-stage ring oscillator; *T-ED Feb 84* 264–269
- Chakraborti, Nirmal B.**, and Sambhu Rakshit. Generation function in uniformly multiplying avalanche diode (Brief); *T-ED Sep 84* 1346–1347
- Cham, Kit M.**, and Shang-Yi Chiang. Device design for the submicrometer p-channel FET with n⁺ polysilicon gate; *T-ED Jul 84* 964–968
- Chamberlain, Savvas G.**, *Guest Ed.*, see Anagnostopoulos, Constantine N., *Guest Ed.*, *T-ED Feb 84* 137–138
- Chamberlain, Savvas G.**, and Jim P. Y. Lee. A novel wide dynamic range silicon photodetector and linear imaging array; *T-ED Feb 84* 175–182
- Chamberlain, Savvas G.**, Asim Husain, and Fritz H. Gaensslen. Nonuniform displacement of MOSFET channel pinchoff; *T-ED Feb 84* 252–256
- Chamberlain, Savvas G.**, see Kumar, Rajendra, *T-ED Jul 84* 928–933
- Chamberlain, Savvas G.**, see Schlig, Eugene S., *T-ED Dec 84* 1907–1908
- Chan, Daniel S. H.**, and Jacob C. H. Phang. A method for the direct measurement of solar cell shunt resistance (Brief); *T-ED Mar 84* 381–383
- Chan, Daniel S. H.**, see Phang, Jacob C. H., *T-ED May 84* 717–718
- Chan, Nelson**, and Tim Thurgate. An impact ionization model for 2D device simulation (Abstr.); *T-ED Dec 84* 1978
- Chang, Chi**, see Liang, Mong-Song, *T-ED Sep 84* 1238–1244
- Chang, Mau-Chung F.**, see Asbeck, Peter M., *T-ED Oct 84* 1377–1380
- Chang, S. T.**, S. A. Lyon, and N. M. Johnson. Analysis of current transport and charge trapping in ultra-thin nitrided oxide MIS capacitors (Abstr.); *T-ED Dec 84* 1972
- Chang, T. Y.**, see Cheng, C. L., *T-ED Dec 84* 1985
- Chatterjee, P. K.**, see Malhi, S. D. S., *T-ED Dec 84* 1981
- Chatterjee, P. K.**, see Banerjee, S. K., *T-ED Dec 84* 1983
- Chattopadhyay, D.**, see Bhattacharyya, Arundhati, *T-ED Dec 84* 1918–1919
- Cheek, Gary C.**, Robert P. Mertens, Roger van Overstraeten, and Louis Frisson. Thick-film metallization for solar cell applications; *T-ED May 84* 602–609
- Chen, C. E.**, see Malhi, S. D. S., *T-ED Dec 84* 1981
- Chen, D. L.**, see Greve, D. W., *T-ED Dec 84* 1982
- Chen, Dan Y.**, and Shaoan Chin. Design considerations for FET-gated power transistors; *T-ED Dec 84* 1834–1837
- Chen, John Y.**, and C. R. Viswanathan. Geometry dependence of dark current in CCD's (Brief); *T-ED Dec 84* 1914–1916
- Chen, John Y.**, see Rensch, David B., *T-ED Dec 84* 1964
- Chen, John Yuan-Tai**. Quadruple-well CMOS for VLSI technology; *T-ED Jul 84* 910–919
- Chen, K. L.**, S. A. Saller, I. A. Groves, and D. B. Scott. Mean time to failure model for hot-carrier-induced degradation (Abstr.); *T-ED Dec 84* 1970–1971
- Chen, Shih-ou**, see Liou, Fu-Tai, *T-ED Dec 84* 1736–1741
- Chen, Shih-ou**, see Liou, Fu-Tai, *T-ED Dec 84* 1972
- Chen, Wen S.**, see Mickelsen, Reid A., *T-ED May 84* 542–546
- Cheng, C. L.**, Larry A. Coldren, B. I. Miller, Andrew S. H. Liao, R. F. Lenehan, and B. Lalevic. A new self-aligned recessed-gate InP MESFET (Brief); *T-ED Jun 84* 840–841
- Cheng, C. L.**, B. Lalevic, A. S. H. Liao, T. Y. Chang, E. A. Cardi, and L. A. Coldren. Enhanced Schottky-gate InGaAs field-effect transistors using e-beam evaporated silicon oxide (Abstr.); *T-ED Dec 84* 1985
- Cheng, Y. C.**, and P. T. Lai. An analytical model for the threshold voltage of a narrow-width MOSFET; *T-ED Dec 84* 1814–1823
- Chevrier, J.**, see Laviron, M., *T-ED Dec 84* 1967
- Chi, Min-Hwa**, see Hu, Chenming, *T-ED Dec 84* 1693–1700
- Chiang, Shang-Yi**, see Cham, Kit M., *T-ED Jul 84* 964–968
- Chiang, Shin-Wu**, see Possin, George E., *T-ED Jan 84* 68–74
- Chilo, Jean**, and Thierry Arnaud. Coupling effects in the time domain for an interconnecting bus in high-speed GaAs logic circuits; *T-ED Mar 84* 347–352
- Chin, Shaoan**, see Chen, Dan Y., *T-ED Dec 84* 1834–1837
- Cho, A. Y.**, see Capasso, F., *T-ED Dec 84* 1972–1973
- Cho, A. Y.**, see Caine, E. J., *T-ED Dec 84* 1984
- Choi, H. K.**, T. H. Windhorn, B.-Y. Tsaur, G. M. Metze, G. W. Turner, and John C. Fan. GaAs MESFET's and AlGaAs double-heterostructure diode lasers fabricated on monolithic GaAs/Si substrates (Abstr.); *T-ED Dec 84* 1988
- Choudhury, A. N. M. Masum**, K. Tabatabaei-Alavi, James C. Vicek, Hiroshi Kanbe, and Clifton G. Fonstad. InGaAs/InP heterojunction bipolar transistors for digital integrated circuits (Abstr.); *T-ED Dec 84* 1980
- Chuang, C. T.** Correction to 'On the current – voltage characteristics of n⁺-p-p⁺ diodes' (Dec 83 1709–1716); *T-ED Jun 84* 843
- Chuang, C. T.**, Maurizio Arizeno, D. Duan-Lee Tang, and Randall D. Isaac. A Schottky-barrier diode with self-aligned floating guard ring; *T-ED Oct 84* 1482–1486
- Chuang, C. T.**, and L. F. Wagner. Probing the minority-carrier quasi-Fermi level in epitaxial Schottky-barrier diodes (Abstr.); *T-ED Dec 84* 1976–1977
- Cirillo, N. C. Jr.**, J. K. Abrokawah, and M. S. Shur. A self-aligned gate process for IC's based on modulation-doped (Al_xGa_{1-x})As/GaAs FET's (Abstr.); *T-ED Dec 84* 1963
- Ciszek, Ted F.**, see Tsuo, Y. S., *T-ED May 84* 614–618
- Clarke, R. Chris**, and Graeme W. Eldridge. Transient capless annealing of ion-implanted GaAs; *T-ED Aug 84* 1077–1082
- Cody, George D.**, see Tiedje, Tom, *T-ED May 84* 711–716

- Coldren, L. A., *see* Cheng, C. L., *T-ED Dec* 84 1985
 Coldren, Larry A., *see* Cheng, C. L., *T-ED Jun* 84 840–841
 Cole, William A., *see* Parpia, Zahir, *T-ED Feb* 84 165–171
 Coleman, Paul D., Mark Wdowik, and Timothy J. Drummond. dc magnetic field effects on a real space transfer heterojunction oscillator; *T-ED Sep* 84 1145–1148
 Comas, J., *see* Kirchoefer, S. W., *T-ED Dec* 84 1985
 Comas, James, *see* Griffin, James A., *T-ED Aug* 84 1096–1099
 Coney, W., *see* Monnig, K. A., *T-ED Dec* 84 1965–1966
 Corboy, John F., *see* Ipri, Alfred C., *T-ED Dec* 84 1741–1748
 Cottrell, Peter E., *see* O, Kenneth K., *T-ED Dec* 84 1976
 Crane, Richard A., *see* Swanson, Richard M., *T-ED May* 84 661–664
 Crowell, C. R., *see* Lee, S. J., *T-ED Dec* 84 1969

D

- Daembkes, Heinrich, W. Brockerhoff, Klaus Heime, and A. Cappy. Improved short-channel GaAs MESFET's by use of higher doping concentration; *T-ED Aug* 84 1032–1037
 Dallos, Andras, and Lawrence C. Pitman. Indirect measurement of temperature of a coated particle cathode of spherical geometry (Brief); *T-ED Mar* 84 379–381
 Darwish, Mohamed N., and Kenneth Board. Optimization of breakdown voltage and on-resistance of VDMOS transistors; *T-ED Dec* 84 1769–1773
 Dat, Rovindra, *see* Lau, Kei May, *T-ED Aug* 84 1086–1089
 Dautremont-Smith, W. C., *see* Koszi, L. A., *T-ED Dec* 84 1910–1912
 Davis, H. E., *see* Malhi, S. D. S., *T-ED Dec* 84 1981
 Dawson, Dale E., *see* Lee, Soong Hak, *T-ED Aug* 84 1068–1071
 Dawson, Dale E., *see* Henry, H. George, *T-ED Aug* 84 1100–1103
 Day, Arthur C., *see* Lowe, Virginia E., *T-ED May* 84 626–629
 De Castro, Ercole, and Massimo Rudan. Integral-equation solution of minority-carrier transport problems in heavily doped semiconductors; *T-ED Jun* 84 785–792
 De Groot, A. W., and Howard C. Card. Charge emission from interface states at silicon grain boundaries by thermal emission and thermionic-field emission—I: Theory; *T-ED Oct* 84 1365–1369
 De Groot, A. W., and Howard C. Card. Charge emission from interface states at silicon grain boundaries by thermal emission and thermionic-field emission—II: Experiment; *T-ED Oct* 84 1370–1376
 De Keersmaecker, Roger F., *see* Groeseneken, Guido, *T-ED Jan* 84 42–53
 De Lacy, John C., *see* Yamaguchi, Tadanori, *T-ED Feb* 84 205–214
 De Man, Hugo J., Moustafa Ghannam, and Robert P. Mertens. Mathematical proof of the validity of reciprocity in one-dimensional bipolar transistors with arbitrary base parameters; *T-ED Dec* 84 1720–1723
 del Alamo, Jesus A., and Richard M. Swanson. Comments, with reply, on 'A method for determining energy gap narrowing in highly doped semiconductors' by Neugroschel, A., et al.; *T-ED Jan* 84 123–125 (Original paper, May 82 894–902)
 del Alamo, Jesús A., and Richard M. Swanson. The physics and modeling of heavily doped emitters; *T-ED Dec* 84 1878–1888
 Delagebeaudeuf, D., *see* Laviron, M., *T-ED Dec* 84 1967
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 Dokos, Dimitri, *see* Preckshot, Nancy E., *T-ED Feb* 84 215–225
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 Drummond, Timothy J., *see* Lee, Kwyro, *T-ED Jan* 84 29–35.
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 Dutton, Robert W., *see* Yu, Zhiping, *T-ED Jun* 84 773–784

E

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 Early, James M., *see* Shoucair, F. S., *T-ED Dec* 84 1866–1872
 East, J. R., *see* Grondin, R. O., *T-ED Jan* 84 21–28
 Eisele, Iganz, *see* Vitanov, Petko, *T-ED Jan* 84 96–100
 Eisen, F. H., *see* Asbeck, P. M., *T-ED Dec* 84 1979
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 Ekstedt, Thomas W., *see* Sodini, Charles G., *T-ED Jan* 84 17–21
 El-Gabaly, Moustafa A., *see* Mains, Richard K., *T-ED Sep* 84 1273–1279
 Elahy, M., *see* Banerjee, S. K., *T-ED Dec* 84 1983
 Eldridge, Graeme W., *see* Clarke, R. Chris, *T-ED Aug* 84 1077–1082
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 Fischer, Russell J., *see* Drummond, Timothy J., *T-ED Sep* 84 1164–1168
 Fischer, Russell J., *see* Arnold, Douglas J., *T-ED Oct* 84 1399–1402
 Fischer, Russell J., *see* Grinberg, Anatoly A., *T-ED Dec* 84 1758–1765
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 Fonash, Stephen J., *Guest Ed.*, and Sigurd Wagner, *Guest Ed.* Foreword to special issue; *T-ED May* 84 522
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 Ford, Jenny M., *see* Sugino, Michael, *T-ED Dec* 84 1823–1829
 Fortmann, Charles, *see* Bube, Richard H., *T-ED May* 84 528–538
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 Fossum, Eric R., and Richard Clark Barker. A linear and compact charge-coupled charge packet differencer/replicator; *T-ED Dec* 84 1784–1789
 Fossum, J. G., *see* Lim, H. K., *T-ED Dec* 84 1983
 Fossum, Jerry G., *see* Lim, Hyung-Kyu, *T-ED Apr* 84 401–408

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Frankie, Dieter, see Schmitt, Felix, *T-ED Aug 84* 1083–1085
Frey, Jeffrey, see Yagi, A., *T-ED Dec 84* 1804–1808
Friedman, Robert, see Maruska, H. Paul, *T-ED Sep 84* 1343–1345
Frison, Louis, see Cheek, Gary C., *T-ED May 84* 602–609
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Fujita, Shigeo, see Sasaki, Akio, *T-ED Jun 84* 805–811
Fujita, Shigeo, see Mitsuyu, Tsuneo, *T-ED Jun 84* 812–817
Fukuda, Yukio, Shigeto Kohda, and Yoshitaka Kitano. A new aluminum pattern formation using substitution reaction of aluminum for polysilicon and its application to MOS device fabrication; *T-ED Jun 84* 828–832
Fukui, Hiroshi, see Yatsuo, Tsutomu, *T-ED Dec 84* 1681–1686
Fukumoto, Masanori, Akihira Shinohara, Shozo Okada, and Koichi Kugimiya. A new MoSi₂/thin poly-Si gate process technology without dielectric degradation of a gate oxide; *T-ED Oct 84* 1432–1439
Fukushima, Yoshifumi, see Uchiike, Heiju, *T-ED Jul 84* 943–950

G

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Gaenssen, Fritz H., see Chamberlain, Savvas G., *T-ED Feb 84* 252–256
Gaeta, Isaura Servín, see Krishna, Surinder, *T-ED Jan 84* 89–95
Gale, Ronald P., see Nichols, Kirby B., *T-ED Dec 84* 1969–1970
Ganguly, Achintya K., and Saeyoung Ahn. Large-signal theory of a two-stage wideband gyro-TWT; *T-ED Apr 84* 474–480
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Gerlach, Willi, see Brieger, K.-P., *T-ED Jun 84* 733–738
Ghannam, Moustafa, see De Man, Hugo J., *T-ED Dec 84* 1720–1723
Ghosal, A., see Bhattacharyya, Arundhati, *T-ED Dec 84* 1918–1919
Gleason, R., see Forbes, L., *T-ED Dec 84* 1986
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Goodman, A. M., see Russell, J. P., *T-ED Dec 84* 1975–1976
Goodman, Douglas S., see Levenson, Marc D., *T-ED Jun 84* 753–763
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Gosmeyer, C. D., see Malhi, S. D. S., *T-ED Dec 84* 1981
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Gossard, A. C., see Hayes, J. R., *T-ED Dec 84* 1979–1980
Gossard, Arthur C., see Luryi, Serge, *T-ED Jun 84* 832–839
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Gough, Paul A., and John A. Slatter. A model for the GTO thyristor during switch-off; *T-ED Dec 84* 1796–1803
Goyal, R., see Moghe, Sanjay B., *T-ED Dec 84* 1931–1937
Grabbe, Paul, see Jackel, Lawrence D., *T-ED Dec 84* 1752–1758
Grant, Wesley N., see Preckshot, Nancy E., *T-ED Feb 84* 215–225
Gray, Peter V., see Love, Robert P., *T-ED Jun 84* 817–820
Gray, Peter V., see Baliga, B. Jayant, *T-ED Jun 84* 821–828
Green, Martin A. Limits on the open-circuit voltage and efficiency of silicon solar cells imposed by intrinsic auger processes; *T-ED May 84* 671–678
Green, Martin A., Andrew W. Blakers, Jiqun Shi, Erik M. Keller, and Stuart R. Wenham. High-efficiency silicon solar cells; *T-ED May 84* 679–683
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Grinolds, Hugh R., see Sodini, Charles G., *T-ED Jan 84* 17–21
Grinolds, Hugh R., see Jolly, Richard D., *T-ED Jun 84* 767–772
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Grondin, R. O., Peter A. Blakey, and J. R. East. Effects of transient carrier transport in millimeter-wave GaAs diodes; *T-ED Jan 84* 21–28

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Grotjohn, Tim, and Bernd Hoefflinger. A parametric short-channel MOS transistor model for subthreshold and strong inversion current; *T-ED Feb 84* 234–246
Groves, I. A., see Chen, K. L., *T-ED Dec 84* 1970–1971
Groves, S. H., see Tsang, Z., *T-ED Dec 84* 1973–1974
Groves, S. H., see Diadiuk, V., *T-ED Dec 84* 1973
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Guha, Shekhar, Chris Braun, Joseph Kung, and Martin Gundersen. Thyatron operation using helium for high-power and high-repetition-rate applications (Brief); *T-ED Jul 84* 992–993
Gundersen, Martin, see Guha, Shekhar, *T-ED Jul 84* 992–993
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Haddad, George I., see Mains, Richard K., *T-ED Sep 84* 1273–1279
Hagiwara, Takaaki, see Aoki, Yukio, *T-ED Oct 84* 1462–1467
Haken, R. A., see Malhi, S. D. S., *T-ED Dec 84* 1981
Han, C. C., see Ferendeci, Altan M., *T-ED Sep 84* 1212–1218
Handy, R., see Rodriguez, B. A., *T-ED Feb 84* 203–205
Hane, Kunio, see Sakai, Tatsuo, *T-ED Jul 84* 873–879
Hanes, Larry K., see Ayasli, Yalcin, *T-ED Dec 84* 1937–1942
Hanes, Larry K., see Ayasli, Yalcin, *T-ED Dec 84* 1943–1947
Hanka, Steven A., see Vu, Tho T., *T-ED Feb 84* 144–156
Hanzal, Brian R., see Vu, Tho T., *T-ED Feb 84* 144–156
Haque, Yusuf A. Design techniques for dynamic range improvement in CMOS circuitry (Corresp.); *T-ED Feb 84* 173–175
Hargrove, M. J., see Larkins, W. T., *T-ED Dec 84* 1966–1967
Hariu, Takashi, see Matsushita, Koichi, *T-ED Aug 84* 1092–1096
Harris, Gary Lynn, see Griffin, James A., *T-ED Aug 84* 1096–1099
Harter, Johann, see Takacs, Dezsoe, *T-ED Mar 84* 279–286
Hasegawa, Hideki, see Sawada, Takayuki, *T-ED Aug 84* 1038–1043
Hasegawa, Hideki, see Seki, Shouhei, *T-ED Dec 84* 1498–1553
Hasegawa, Hideki, and Shouhei Seki. Analysis of interconnection delay on very high-speed LSI/VLSI chips using an MIS microstrip line model; *T-ED Dec 84* 1954–1960
Hashiguchi, Kazuo, see Watanabe, Takashi, *T-ED Feb 84* 183–188
Hashimoto, Norikazu, see Sunami, Hideo, *T-ED Jun 84* 746–753
Hashizume, N., see Matsumoto, K., *T-ED Dec 84* 1963
Hashizume, N., see Matsumoto, K., *T-ED Dec 84* 1987
Hashizume, Nobuo, see Awano, Yuji, *T-ED Apr 84* 448–452
Hauser, John R., see Arora, Narain D., *T-ED Apr 84* 430–434
Hava, Shlomo, see Kopeika, N. S., *T-ED Sep 84* 1198–1206
Hayashi, Izuo. Heterostructure lasers; *T-ED Nov 84* 1630–1642
Hayashi, Y., see Iida, H., *T-ED May 84* 718–719
Hayes, J. R., R. F. Leheny, H. Temkin, A. C. Gossard, and W. Wiegmann. Radiative recombination in heterojunction bipolar transistors (Abstr.); *T-ED Dec 84* 1979–1980
Hazout, Eli, see Kopeika, N. S., *T-ED Sep 84* 1198–1206
Hegedus, Steven S. The photoresponse of CdS/CuInSe₂ thin-film heterojunction solar cells; *T-ED May 84* 629–633
Heikkila, Walter W., see Preckshot, Nancy E., *T-ED Feb 84* 215–225
Heime, Klaus, see Daembkes, Heinrich, *T-ED Aug 84* 1032–1037
Helix, Max J., see Lee, Kang, *T-ED Mar 84* 390–393
Helix, Max J., see Vu, Tho T., *T-ED Feb 84* 144–156
Helstrom, Carl W. Computation of output electron distributions in avalanche photodiodes; *T-ED Jul 84* 955–958
Hendel, R. H., see Pei, S. S., *T-ED Dec 84* 1962
Hendel, R. H., see Feuer, M. D., *T-ED Dec 84* 1967–1968
Hendel, Rudi H., see Luryi, Serge, *T-ED Jun 84* 832–839
Henderson, T., see Fischer, Russell J., *T-ED Dec 84* 1963–1964
Henderson, Timothy S., see Fischer, Russell J., *T-ED Aug 84* 1028–1032
Henderson, Timothy S., see Arnold, Douglas J., *T-ED Oct 84* 1399–1402
Henry, H. George, Dale E. Dawson, Zachary J. Lemnios, and Heborg Kim. Hot-plate alloying for ohmic contacts to GaAs; *T-ED Aug 84* 1100–1103
Hess, K., see Robbins, V. M., *T-ED Dec 84* 1977–1978
Hester, R. K., see Malhi, S. D. S., *T-ED Dec 84* 1981
Hickmott, Thomas W. Temperature dependence of FET properties for Cr-doped and LEC semi-insulating GaAs substrates; *T-ED Jan 84* 54–62
Hicks, Michael C., see Maruska, H. Paul, *T-ED Sep 84* 1343–1345
Hide, Ichiro, see Maeda, Yasuhiro, *T-ED May 84* 708–710
Hirayama, Masahiro, see Matsuoka, Yutaka, *T-ED Aug 84* 1062–1067
Hirayama, Masahiro, see Ino, Masayuki, *T-ED Sep 84* 1139–1144
Hiroshima, Yoshimitsu, see Senda, Kohji, *T-ED Sep 84* 1324–1328
Hiroshima, Yoshimitsu, see Senda, Kohji, *T-ED Dec 84* 1873–1877
Hirsh, Israel, see Kopeika, N. S., *T-ED Sep 84* 1198–1206

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 Hite, L., see Malhi, S. D. S., *T-ED Dec 84* 1981
 Hoefflinger, Bernd, Sie T. Liu, and Branislav Vajdic. A three-dimensional CMOS design methodology (Corresp.); *T-ED Feb 84* 171–173
 Hoefflinger, Bernd, see Grotjohann, Tim, *T-ED Feb 84* 234–246
 Hoffman, Richard A., see Sinharoy, Samar, *T-ED Aug 84* 1090–1092
 Hohkawa, Kohji, Junsaku Nitta, and Akira Ishida. A Josephson adder employing high-gain direct-coupled logic gate; *T-ED Jul 84* 983–987
 Hojo, A., see Yoshida, J., *T-ED Dec 84* 1979
 Hollis, Mark A., see Nichols, Kirby B., *T-ED Dec 84* 1969–1970
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 Hoshino, Yasushi, see Tateishi, Kazuyoshi, *T-ED Jun 84* 793–796
 Howard, Richard E., see Jackel, Lawrence D., *T-ED Dec 84* 1752–1758
 Hsiao, Y. Roger, see Mickelsen, Reid A., *T-ED May 84* 542–546
 Hu, Chenming, see Tam, Simon, *T-ED Sep 84* 1116–1125
 Hu, Chenming, see Terrill, Kyle W., *T-ED Sep 84* 1152–1155
 Hu, Chenming, see Liang, Mong-Song, *T-ED Sep 84* 1238–1244
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 Hua, Q. H., see Yang, E. S., *T-ED Dec 84* 1981
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 Huang, Ruey-Shing, see Huang, Rei-Min, *T-ED Jul 84* 1001–1004
 Huber, Walter, see Bube, Richard H., *T-ED May 84* 528–538
 Huebener, Rudolf P., see Parisi, Jürgen, *T-ED Mar 84* 310–314
 Hull, Joseph F. A young engineer enters the microwave tube field during World War II; *T-ED Nov 84* 1611–1613
 Hunter, A. T., H. M. Olsen, R. P. Bryan, R. E. Lee, and H. V. Winston. Substrate effects on the performance of MESFET's fabricated on undoped LEC GaAs and In-alloyed GaAs (Abstr.); *T-ED Dec 84* 1987
 Hunter, W. R., see Teng, Clarence W., *T-ED Dec 84* 1966
 Hurd, Jeff L., see Tsuo, Y. S., *T-ED May 84* 614–618
 Husain, Asim, see Chamberlain, Savvas G., *T-ED Feb 84* 252–256
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 Hwang, Kyuwoon, and David H. Navon. Breakdown voltage optimization of silicon p–n–n planar junction diodes; *T-ED Sep 84* 1126–1135
 Hwang, Wei, see So, S. M., *T-ED May 84* 696–707
 Hynecek, Jaroslave. Design and performance of a low-noise charge-detection amplifier for VPCCD devices; *T-ED Dec 84* 1713–1719

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 Iida, H., T. Mishuku, and Y. Hayashi. Optical confinement type a-Si:H solar cell using milky tin oxide on glass (Brief); *T-ED May 84* 718–719
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 Ino, Masayuki, Minoru Togashi, Masahiro Hirayama, Katsuhiro Kurumada, and Masamichi Ohmori. Design of GaAs 1K bit static RAM; *T-ED Sep 84* 1139–1144
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 Ishibashi, T., see Sugeta, T., *T-ED Dec 84* 1978–1979
 Ishida, Akira, see Yamada, Hajime, *T-ED Mar 84* 307–310
 Ishida, Akira, see Miyahara, Kazunori, *T-ED Jul 84* 888–894
 Ishida, Akira, see Hohkawa, Kohji, *T-ED Jul 84* 983–987
 Ishida, Satoru, see Ishii, Yasunobu, *T-ED Jun 84* 800–804
 Ishida, Satoru, see Ishii, Yasunobu, *T-ED Aug 84* 1051–1056
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 Kano, Gota, see Ueda, Daisuke, *T-ED Apr 84* 416–420
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 Kitano, Yoshitaka, see Fukuda, Yukio, *T-ED Jun* 84 828–832
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 Ko, Ping-Keung, see Jackel, Lawrence D., *T-ED Dec* 84 1752–1758
 Kobayashi, Nobuyoshi, see Iwata, Seichi, *T-ED Sep* 84 1174–1179
 Kohda, Shigeto, see Fukuda, Yukio, *T-ED Jun* 84 828–832
 Kohno, Akiyoshi, see Ishihara, Yasuo, *T-ED Jan* 84 83–88
 Kohno, Akiyoshi, see Teranishi, Nobukazu, *T-ED Dec* 84 1829–1833
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 Kurogi, Yukinori, see Endo, Nobuhiro, *T-ED Sep* 84 1283–1288
 Kurosawa, Susumu, see Terada, Kazuo, *T-ED Sep* 84 1319–1324
 Kurumada, Katsuhiko, see Ino, Masayuki, *T-ED Sep* 84 1139–1144
 Kurumada, Katsuhiko, see Murase, Katsumi, *T-ED Dec* 84 1980–1981
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 Lam, H. W., see Banerjee, S. K., *T-ED Dec* 84 1983
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 Lee, Chun-Teh, see Bube, Richard H., *T-ED May* 84 528–538
 Lee, Gary M., see Vu, Tho T., *T-ED Feb* 84 144–156
 Lee, Jim P. Y., see Chamberlain, Savvas G., *T-ED Feb* 84 175–182
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 Morimoto, Mitsutaka, see Okabayashi, Hidekazu, *T-ED Sep 84* 1329–1334
 Morimoto, Seiichi, see Yamaguchi, Tadanori, *T-ED Feb 84* 205–214
 Morizuka, K., see Yoshida, J., *T-ED Dec 84* 1979
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 Morkog, Hadis, see Grinberg, Anatoly A., *T-ED Dec 84* 1758–1765
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 Navon, David H., see Hwang, Kyuwoo, *T-ED Sep 84* 1126–1135
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 Navon, David H., see Park, Young-June, *T-ED Dec 84* 1724–1730
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 Nelson, Roderick D., see Vu, Tho T., *T-ED Feb 84* 144–156
 Neppi, Franz, see Schwabe, Ulrich, *T-ED Jul 84* 988–992
 Neugroschel, Arnost, see Gonzalez, Franklin N., *T-ED Apr 84* 413–416
 Neugroschel, Arnost, see Jung, Taewon, *T-ED May 84* 588–595
 Neureuther, Andrew R., see Kim, Deok Jung, *T-ED Dec 84* 1730–1736
 Nichols, David N., see Anagnostopoulos, Constantine N., *T-ED Feb 84* 225–231
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 Oda, Eiji, see Teranishi, Nobukazu, *T-ED Dec 84* 1829–1833
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 Ohashi, Hiromichi, see Nakagawa, Akio, *T-ED Mar 84* 273–279
 Ohata, D., see Baba, T., *T-ED Dec 84* 1962
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 Ohnishi, T., see Nakayama, Y., *T-ED Dec 84* 1987–1988
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 Oldham, William G., see Sodini, Charles G., *T-ED Jan 84* 17–21
 Oldham, William G., see Kim, Deok Jung, *T-ED Dec 84* 1730–1736
 Oleszek, G. M., see Kasley, K. L., *T-ED Sep 84* 1341–1343
 Olsen, H. M., see Hunter, A. T., *T-ED Dec 84* 1987
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 Otsuki, Tatsuo, see Ohta, Issey, *T-ED Mar 84* 389–390
 Outlaw, R. A., see Wilson, John W., *T-ED Apr 84* 421–422
 Owyang, King W., see Adler, Michael S., *T-ED Nov 84* 1570–1591

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- Schroeder, James E., see Stone, Dona C., *T-ED Feb 84* 189–195
- Schultz, Dale, see Preckshot, Nancy E., *T-ED Feb 84* 215–225
- Schwabe, Ulrich, see Vitanov, Petko, *T-ED Jan 84* 96–100
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- Shah, Rajiv R., see Kim, Dae M., *T-ED Apr 84* 480–493
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- Shi, Jiqun, see Green, Martin A., *T-ED May 84* 679–683
- Shibata, Yukio, see Matsushita, Koichi, *T-ED Aug 84* 1092–1096
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- Shinohara, Akihira, see Fukumoto, Masanori, *T-ED Oct 84* 1432–1439
- Shinozaki, Satoru, see Watanabe, Satoru, *T-ED Dec 84* 1921–1925
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- Shono, K., see Sugiura, S., *T-ED Dec 84* 1983–1984
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- Shur, Michael S., see Vu, Tho T., *T-ED Feb 84* 144–156
- Shur, Michael S., see Lee, Kang, *T-ED Mar 84* 390–393
- Shur, Michael S., see Hack, Michael, *T-ED May 84* 539–542
- Shur, Michael S., see Drummond, Timothy J., *T-ED Sep 84* 1164–1168
- Shur, Michael S., see Lee, Kwyro, *T-ED Oct 84* 1394–1398
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- Silard, Andrei P. Switching characteristics of 45-A double-interdigitated GTO thyristors; *T-ED Sep 84* 1230–1237
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- Sinclair, Robert, see Bube, Richard H., *T-ED May 84* 528–538
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- Sinton, Ronald A., see Swanson, Richard M., *T-ED May 84* 661–664
- Sites, James R., see Potter, Richard T., *T-ED May 84* 571–577
- Slatter, John A., see Gough, Paul A., *T-ED Dec 84* 1796–1803
- Slatter, John A. G., see Fisher, Carole A., *T-ED Sep 84* 1299–1308
- Smith, Allan R., see Stone, Dona C., *T-ED Feb 84* 189–195
- Smith, Gregory C., see Tiku, Shiban K., *T-ED Jan 84* 105–108
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- Srivastava, Ram Sahai, see Joshi, Dinesh Prasad, *T-ED Jul 84* 920–927
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- Stevens, Eugene H., see Kubena, Randall L., *T-ED Sep 84* 1186–1189
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- Suyama, K., see Nakayama, Y., *T-ED Dec 84* 1987–1988
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- Suzuki, Shun'ichi, see Terada, Kazuo, *T-ED Sep 84* 1308–1313
- Suzuki, Shun'ichi, see Terada, Kazuo, *T-ED Sep 84* 1319–1324
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Swanson, Richard M., *see* del Alamo, Jesús A., *T-ED Dec 84* 1878–1888
Swartz, Robert G., *see* Jackel, Lawrence D., *T-ED Dec 84* 1752–1758
Swirhun, S., *see* Sangiorgi, E., *T-ED Dec 84* 1967
Swirhun, Stanley E., *see* Swanson, Richard M., *T-ED May 84* 661–664

T

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Tabatabaie, Nader, *see* Stillman, Gregory E., *T-ED Nov 84* 1643–1655
Tabatabaie-Alavi, K., *see* Choudhury, A. N. M. Masum, *T-ED Dec 84* 1980
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Takacs, Dezsoe, Christoph Werner, Johann Harter, and Ulrich Schwabe. Surface induced latchup in VLSI CMOS circuits; *T-ED Mar 84* 279–286
Takagi, Hiromitsu, *see* Ueda, Daisuke, *T-ED Apr 84* 416–420
Takahashi, Haruo, Hiroshi Mishihara, and Jiro Koyama. Light-detectable function of the negative resistance characteristic presented by an optocoupler; *T-ED Jul 84* 951–954
Takahashi, Toru, *see* Sato, Fumihiro, *T-ED Feb 84* 139–143
Takeuchi, Ei-chi, *see* Ishihara, Yasuo, *T-ED Jan 84* 83–88
Takeuchi, Susumu, *see* Kashiwaki, Tadashi, *T-ED Oct 84* 1403–1407
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Tamura, Massao, *see* Waja, Yasuo, *T-ED Dec 84* 1964–1965
Taneya, Mototaka, *see* Sasaki, Akio, *T-ED Jun 84* 805–811
Tang, D. Duan-Lee, *see* Chuang, C. T., *T-ED Oct 84* 1482–1486
Tang, Denny D., *see* Ning, Tak H., *T-ED Apr 84* 409–412
Tang, J., *see* Robbins, V. M., *T-ED Dec 84* 1977–1978
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Tanigawa, Hiroshi, *see* Ishihara, Yasuo, *T-ED Jan 84* 83–88
Tannenwald, P. E., *see* Sollner, T. C. L. G., *T-ED Dec 84* 1985
Tanno, Kohetsu, *see* Endo, Nobuhiro, *T-ED Sep 84* 1283–1288
Tanno, Kohetsu, *see* Terada, Kazuo, *T-ED Sep 84* 1308–1313
Tateishi, Kazuyoshi, and Yasushi Hoshino. Three-layer photoreceptor (Se-Se-Se) with high sensitivity in the long-wavelength region; *T-ED Jun 84* 793–796
Taylor, Geoffrey W., *Guest Ed.* Foreword to special section; *T-ED Nov 84* 1522
Temes, G. C., *see* Rodriguez, B. A., *T-ED Feb 84* 203–205
Temkin, H., *see* Hayes, J. R., *T-ED Dec 84* 1979–1980
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Terada, Tomoyuki, *see* Iwata, Seichi, *T-ED Sep 84* 1174–1179
Terakawa, Sumio, *see* Senda, Kohji, *T-ED Sep 84* 1324–1328
Terakawa, Sumio, *see* Senda, Kohji, *T-ED Dec 84* 1873–1877
Teramoto, Iwao, *see* Ohta, Issey, *T-ED Mar 84* 389–390
Teranishi, Nobukazu, *see* Ishihara, Yasuo, *T-ED Jan 84* 83–88
Teranishi, Nobukazu, Akiyoshi Kohno, Yasuo Ishihara, Eiji Oda, and Kouichi Arai. An interline CCD image sensor with reduced image lag; *T-ED Dec 84* 1829–1833
Terasawa, Yoshio, *see* Shimizu, Yoshiteru, *T-ED Sep 84* 1314–1319
Terrill, Kyle W., and Chenming Hu. Substrate resistance calculation for latchup modeling; *T-ED Sep 84* 1152–1155
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Thoma, Morgan J., and Charles R. Westgate. A new ac measurement technique to accurately determine MOSFET constants; *T-ED Sep 84* 1113–1116
Thomas, Robert C. Czochralski silicon; *T-ED Nov 84* 1547–1549
Thomson, D. J., *see* Mbewe, Dominic Jacob, *T-ED May 84* 523–527
Thorpe, Thomas, *see* Bube, Richard H., *T-ED May 84* 528–538

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Tiku, Shiban K., and Gregory C. Smith. Choice of dielectrics for TFEL displays; *T-ED Jan 84* 105–108
Ting, Chung-Yu, *see* Iyer, Subramanian S., *T-ED Oct 84* 1468–1471
Tischler, Mike, *see* Fair, Richard B., *T-ED Sep 84* 1180–1185
Tiwari, S., *see* Wang, W. I., *T-ED Dec 84* 1968–1969
Tiwari, Sandip. Threshold and sheet concentration sensitivity of high electron mobility transistors; *T-ED Jul 84* 879–888
Tobin, Stephen P., *see* Spitzer, Mark B., *T-ED May 84* 546–550
Togashi, Minoru, *see* Ino, Masayuki, *T-ED Sep 84* 1139–1144
Tokunaga, Yukio, *see* Ohya, Jun, *T-ED Sep 84* 1258–1263
Tomizawa, Kazutaka, *see* Awano, Yuji, *T-ED Apr 84* 448–452
Tomizawa, Masaaki, Masao Uchida, and Takayuki Sugeta. Improvement in GaAs MESFET drain conductance by a steplike-gate structure; *T-ED Apr 84* 435–439
Tomizawa, Masaaki, *see* Yokoyama, Kiyoyuki, *T-ED Sep 84* 1222–1229
Topich, James A. Long-term retention of SNOS nonvolatile memory devices (Brief); *T-ED Dec 84* 1908–1910
Towers, Malcolm S., *see* Board, Kenneth, *T-ED Jan 84* 75–80
Toyabe, Toru, *see* Sunami, Hideo, *T-ED Jun 84* 746–753
Toyabe, Toru, *see* Aoki, Yukio, *T-ED Oct 84* 1462–1467
Trabka, Eugene A., *see* Burkey, Bruce C., *T-ED Apr 84* 423–429
Tredwell, Timothy J., *see* Burkey, Bruce C., *T-ED Apr 84* 423–429
Troutman, R. R., *see* Larkins, W. T., *T-ED Dec 84* 1966–1967
Troutman, Ronald R., and Hans P. Zappe. Layout and bias considerations for preventing transiently triggered latchup in CMOS; *T-ED Mar 84* 315–321
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Tsang, Z., J. N. Walpole, S. H. Groves, and Z. L. Liu. 14-GHz operation of Q-switched diode lasers (Abstr.); *T-ED Dec 84* 1973–1974
Tsaur, B.-Y., *see* Choi, H. K., *T-ED Dec 84* 1988
Tsuchiya, Hiroshi, *see* Uchiike, Heiju, *T-ED Jul 84* 943–950
Tsuji, Kazuhiko, Masaru Sasago, and Koichi Kugimura. Submicrometer optical lithography using a double-layer resist by a single development technology; *T-ED Dec 84* 1861–1866
Tsuo, Y. S., Jeff L. Hurd, Richard J. Matson, and Ted F. Ciszek. Electron channeling and EBIC studies of edge-supported pulling silicon sheets; *T-ED May 84* 614–618
Tsuya, Hideki, *see* Endo, Nobuhiro, *T-ED Sep 84* 1283–1288
Tu, C. W., *see* Pei, S. S., *T-ED Dec 84* 1962
Tu, C. W., *see* Feuer, M. D., *T-ED Dec 84* 1967–1968
Tung, Pham N., *see* Laviron, M., *T-ED Dec 84* 1967
Turner, G. W., *see* Choi, H. K., *T-ED Dec 84* 1988
Turtudau, Florian, Silard, Andrei P., *T-ED Mar 84* 322–328
Tyler, J. U., *see* Meulenbergh, A., *T-ED May 84* 720–721

U

- Uchida, Masao**, *see* Tomizawa, Masaaki, *T-ED Apr 84* 435–439
Uchikata, Yasutaka, *see* Naruke, Yasuo, *T-ED Mar 84* 362–366
Uchiike, Heiju, Hiroshi Tsuchiya, Noriyuki Awaji, Tsutae Shinoda, and Yoshifumi Fukushima. Characteristics of discharge pattern in surface-discharge ac plasma display panels; *T-ED Jul 84* 943–950
Ueda, Daisuke, Hiromitsu Takagi, and Goto Kano. A new vertical double diffused MOSFET—The self-aligned terraced-gate MOSFET; *T-ED Apr 84* 416–420
Unno, Hideyuki, *see* Imai, Kazuo, *T-ED Mar 84* 297–302
Urquhart, James S., *see* Saul, Peter, *T-ED Feb 84* 196–202

V

- Vajdic, Branislav**, *see* Hoefflinger, Bernd, *T-ED Feb 84* 171–173
Valois, Anthony J., *see* Lee, Kwyro, *T-ED Oct 84* 1394–1398
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van der Ziel, Aldert, and G. Bosman. Accurate expression for the noise temperature of common emitter microwave transistors; *T-ED Sep 84* 1280–1283
van der Ziel, Aldert, *see* Duh, K. H., *T-ED Sep 84* 1345–1346
van der Ziel, Aldert, *see* Lee, Kwyro, *T-ED Oct 84* 1394–1398
van der Ziel, Aldert, *see* Zhu, Xichen C., *T-ED Oct 84* 1408–1413
van Overstraeten, Roger, *see* Cheek, Gary C., *T-ED May 84* 602–609
Varker, Charles J., *see* Schroder, Dieter K., *T-ED Apr 84* 462–467
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 Victorey, John P., *see* Preckshot, Nancy E., *T-ED Feb 84* 215–225
 Vinal, Albert W., and Nino A. Masnari. Operating principles of bipolar transistor magnetic sensors; *T-ED Oct 84* 1486–1494
 Viswanathan, C. R., *see* Chen, John Y., *T-ED Dec 84* 1914–1916
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Vu, Tho T., *see* Lee, Kang, *T-ED Mar 84* 390–393

W

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Wada, Tsutomu, *see* Yachi, Toshiaki, *T-ED Dec 84* 1748–1752
 Wagemann, Hans-Günther, *see* Böhm, Markus, *T-ED Oct 84* 1440–1446
 Wagner, L. F., *see* Chuang, C. T., *T-ED Dec 84* 1976–1977
 Wagner, Sigurd, *Guest Ed.*, *see* Fonash, Stephen J., *Guest Ed.*, *T-ED May 84* 522
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 Wallinga, Hans, *see* Penning de Vries, René G. M., *T-ED Oct 84* 1454–1462
 Walpole, J. N., *see* Tsang, Z., *T-ED Dec 84* 1973–1974
 Wang, Faa-Ching, *see* Miller, Daniel, *T-ED Dec 84* 1985–1986
Wang, Faa-Ching, Marina Bujatti, Dan Miller, Dan Morgan, and George Patterson. Performance of GaAs MESFET's directly ion implanted on gettered substrates (Abstr.); *T-ED Dec 84* 1986–1987
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 Watakabe, Yachiro, *see* Kashiwaki, Tadashi, *T-ED Oct 84* 1403–1407
 Watanabe, Makoto. Semiconductor industry in Japan—Past and present; *T-ED Nov 84* 1562–1570
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 Watanabe, Yoshiro. Threshold voltage instability of a static RAM under 7°K operation; *T-ED Dec 84* 1898–1901
 Watanabe, Takashi, Kazuo Hashiguchi, Toshiaki Yamano, Jun-ichi Nakai, Shigeishi Miyatake, Osamu Matsui, and Katsunobu Awane. A CCD color signal separation IC for single-chip color imagers; *T-ED Feb 84* 183–188
 Wdowik, Mark, *see* Coleman, Paul D., *T-ED Sep 84* 1145–1148
 Webb, P., *see* Robbins, V. M., *T-ED Dec 84* 1977–1978
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 Weiler, Margaret H., and Yalcin Ayasli. dc and microwave models for $\text{Al}_x\text{Ga}_{1-x}\text{As}/\text{GaAs}$ high electron mobility transistors; *T-ED Dec 84* 1854–1861
 Wenham, Stuart R., *see* Green, Martin A., *T-ED May 84* 679–683
 Werner, Christoph, *see* Takacs, Dezsoe, *T-ED Mar 84* 279–286
 Westbrook, L. D., *see* Nelson, A. W., *T-ED Dec 84* 1974
 Westgate, Charles R., *see* Thoma, Morgan J., *T-ED Sep 84* 1113–1116
 White, M. H., *see* Booth, Richard V. H., *T-ED Feb 84* 247–251
 Whitfield, James D., *see* Schroeder, Dieter K., *T-ED Apr 84* 462–467
 Wiegmann, W., *see* Hayes, J. R., *T-ED Dec 84* 1979–1980
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 Wilson, Ralph A., III, *see* Baumert, Robert J., *T-ED Feb 84* 160–165
 Windhorn, T. H., *see* Choi, H. K., *T-ED Dec 84* 1988
 Wingmann, W., *see* Kiehl, R. A., *T-ED Dec 84* 1968
 Winston, H. V., *see* Hunter, A. T., *T-ED Dec 84* 1987
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 Womack, R. H., *see* Banerjee, S. K., *T-ED Dec 84* 1983
 Wong, Kwok Y., *see* Anagnostopoulos, Constantine N., *T-ED Feb 84* 225–231
 Wong, S. Simon, *see* Sodini, Charles G., *T-ED Jan 84* 17–21
 Wong, Y. K., *see* Phang, Jacob C. H., *T-ED May 84* 717–718
 Woodbury, H. Hugh, *see* Wei, Ching-Yeu, *T-ED Dec 84* 1773–1780
 Wordeman, Matthew R., *see* Baccaran, Giorgio, *T-ED Apr 84* 452–462
 Wordeman, Matthew R., *see* Sun, Jack Y. C., *T-ED Dec 84* 1970
 Wortman, Jimmie J., *see* Fair, Richard B., *T-ED Sep 84* 1180–1185
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Y

- Yablonovitch, Eli, *see* Tiedje, Tom, *T-ED May 84* 711–716
 Yachi, Toshiaki, Tadashi Serikawa, and Tsutomu Wada. A new field isolation technology employing lift-off patterning of sputtered SiO_2 films; *T-ED Dec 84* 1748–1752
 Yagi, A., and Jeffrey Frey. Effects of injection resistance on the performance of very-short-channel MOSFET's; *T-ED Dec 84* 1804–1808
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 Yamagishi, C., *see* Ishida, T., *T-ED Dec 84* 1988
 Yamaguchi, Ken, *see* Horiuchi, Masatada, *T-ED Jun 84* 739–746
 Yamaguchi, Ken. Mathematical modeling of semiconductor-on-insulator (SOI) device operation; *T-ED Jul 84* 977–982
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 Yamamoto, Masafumi, *see* Miyahara, Kazunori, *T-ED Jul 84* 888–894
 Yamamoto, Naoki, *see* Iwata, Seichi, *T-ED Sep 84* 1174–1179
 Yamamoto, Shigehiko, *see* Taguchi, Sadanori, *T-ED Jul 84* 900–903
 Yamano, Toshiaki, *see* Watanabe, Takashi, *T-ED Feb 84* 183–188
 Yamashita, Tsutomu, *see* Bube, Richard H., *T-ED May 84* 528–538
 Yamauchi, Yoshiaki, *see* Miyahara, Kazunori, *T-ED Jul 84* 888–894
 Yang, D. K., *see* Yang, E. S., *T-ED Dec 84* 1981
 Yang, E. S., Q. H. Hua, D. K. Yang, and G. S. Yang. Amorphous silicon as a tunneling barrier (Abstr.); *T-ED Dec 84* 1981
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 Yano, Hiroshi, *see* Sasaki, Akio, *T-ED Jun 84* 805–811
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 Yatsuo, Tsutomu, Takahiro Nagano, Hiroshi Fukui, Masahiro Okamura, and Shuroku Sakurada. Ultrahigh-voltage high-current gate turn-off thyristors; *T-ED Dec 84* 1681–1686
 Yeh, Fon-Shan, *see* Huang, Rei-Min, *T-ED Jul 84* 1001–1004
 Yeow, Yew Tong, *see* Liang, Mong-Song, *T-ED Sep 84* 1238–1244
 Yokoyama, Kiyoyuki, Masaaki Tomizawa, and Akira Yoshii. Accurate modeling of AlGaAs/GaAs heterostructure bipolar transistors by two-dimensional computer simulation; *T-ED Sep 84* 1222–1229
 Yokoyama, Naoki, *see* Onodera, Hiroyuki, *T-ED Dec 84* 1808–1812
 Yokoyama, Takashi, *see* Maeda, Yasuhiro, *T-ED May 84* 708–710
 Yoshida, J., M. Kurata, M. Obara, K. Morizuka, M. Mashita, and A. Hojo. Emitter-base bandgap grading effects on GaAlAs/GaAs heterojunction bipolar transistors (Abstr.); *T-ED Dec 84* 1979
 Yoshida, Jiro, *see* Kurata, Mamoru, *T-ED Apr 84* 467–473
 Yoshida, T., *see* Suguri, S., *T-ED Dec 84* 1983–1984
 Yoshii, Akira, *see* Yokoyama, Kiyoyuki, *T-ED Sep 84* 1222–1229
 Yu, Zhiping, Bruno Ricco, and Robert W. Dutton. A comprehensive analytical and numerical model of polysilicon emitter contacts in bipolar transistors; *T-ED Jun 84* 773–784

Z

- Zafar, Naeem, *see* Vu, Tho T., *T-ED Feb 84* 144–156
 Zappe, Hans P., *see* Troutman, Ronald R., *T-ED Mar 84* 315–321
 Zhang, X. N., *see* Zhu, Xichen C., *T-ED Oct 84* 1408–1413
 Zhu, Xichen C., *see* Duh, K. H., *T-ED Sep 84* 1345–1346
 Zhu, Xichen C., *see* Lee, Kwyro, *T-ED Oct 84* 1394–1398
 Zhu, Xichen C., X. N. Zhang, Aldert van der Ziel, and Carl O. Bozler. Low-frequency noise in permeable base transistors; *T-ED Oct 84* 1408–1413
 Zigadlo, J. P., *see* Kasley, K. L., *T-ED Sep 84* 1341–1343
 Zimmer, Günter, *see* Dobos, Karoly, *T-ED Apr 84* 508–510
 Zommer, Nathan D., *see* Baliga, B. Jayant, *T-ED Jun 84* 821–828

† Check author entry for subsequent corrections/comments

SUBJECT INDEX

A

Absorbing media; cf. Optical propagation, absorbing media
Active filters, *RC*; cf. Switched-capacitor filters

Addition

high-speed two-bit dual rail adder using asymmetrical interference device Josephson logic gate. *Yamada, Hajime, +, T-ED Mar 84* 307–310

wide-margin Josephson adder employing high-grain direct-coupled logic gate. *Hokkawa, Kohji, +, T-ED Jul 84* 983–987

Alpha-particle radiation effects; cf. Integrated-circuit radiation effects**Aluminum conductors, integrated circuits**

Al alloys with Ti, W and Cu for multilayer interconnections for VLSI (Abstr.). *Gardner, Don, +, T-ED Dec 84* 1965

fabrication of self-aligned Al-gate MOSFETs by Al pattern formation process using substitution reaction of Al for polysilicon. *Fukuda, Yukio, +, T-ED Jun 84* 828–832

Aluminum materials/devices; cf. Specific topic**Amorphous semiconductor materials/devices**

amorphous Si – Ge – B gate GaAs FETs with large barrier heights and transconductance (Abstr.). *Murase, Katsumi, +, T-ED Dec 84* 1980–1981

influence of wavelength of incident light on shunt conductance and fill factor in amorphous Si solar cells. *Maruska, H. Paul, +, T-ED May 84* 551–558

modification of characteristics of metal – semiconductor contacts by insertion of ultrathin amorphous Si layer at junction interface (Abstr.). *Yang, E. S., +, T-ED Dec 84* 1981

optical confinement type a-Si:H solar cell using milky tin oxide on glass substrate. *Iida, H., +, T-ED May 84* 718–719

optically controlled amorphous Si photosensitive device. *Maruska, H. Paul, +, T-ED Sep 84* 1343–1345

role of B profiling in enhancing performance of amorphous-Si-based p-i-n solar cells. *Hack, Michael, +, T-ED May 84* 539–542

theory of operation of amorphous-silicon charge-coupled devices. *Naruke, Yasuo, +, T-ED Mar 84* 362–366

Amplifier noise

design and performance of low-noise charge-detection amplifier for virtual phase charge-coupled devices. *Hynecek, Jaroslave, T-ED Dec 84* 1713–1719

Amplifiers; cf. Distributed amplifiers; Feedback amplifiers; Infrared amplifiers; Millimeter-wave amplifiers; MOSFET amplifiers; Optical amplifiers; Pulse amplifiers; Tuned amplifiers**Analog integrated circuits;** cf. Bipolar integrated circuits, analog; CMOS integrated circuits, analog; Microwave FET integrated circuits; MOS integrated circuits, analog**Annealing;** cf. Thermal factors**Arithmetic**

quasi-three-dimensionally charge-coupled circuit for performing charge packet differencing operation. *Fossum, Eric R., +, T-ED Dec 84* 1784–1789

Arithmetic; cf. Addition; Multiplication**Arrays;** cf. Logic arrays**Avalanche breakdown**

breakdown phenomena in Si n-type JFET. *Sakai, Tatsuo, +, T-ED Jul 84* 873–879

breakdown voltage design considerations in VDMOS structures. *Mena, José G., +, T-ED Jan 84* 109–113

breakdown voltage optimization of Si p – π – n planar junction diodes. *Hwang, Kyuwoon, +, T-ED Sep 84* 1126–1135

Avalanche diodes

generation function in uniformly multiplying avalanche diode. *Chakraborti, Nirmal B., +, T-ED Sep 84* 1346–1347

Avalanche diodes; cf. IMPATT diodes**Avalanche photodiodes**

breakdown characteristics of Si multi-element avalanche photodiode array; two-dimensional computer simulation. *Kumar, Rajendra, +, T-ED Jul 84* 928–933

computation of output electron distributions in avalanche photodiodes. *Helstrom, Carl W., T-ED Jul 84* 955–958

fabrication of multielement arrays of reachthrough avalanche photodiodes. *Webb, Paul P., +, T-ED Sep 84* 1206–1212

history of development of III – V compound semiconductor optical detectors. *Stillman, Gregory E., +, T-ED Nov 84* 1643–1655

Avalanche photodiodes; cf. Optical fiber receivers

B

Bandpass filters

micropower monolithic filters realized using bipolar-compatible JFET technology; switched-capacitor and continuous analog filters. *Parpia, Zahir, +, T-ED Feb 84* 165–171

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evolution of power device technology. *Adler, Michael S., +, T-ED Nov 84* 1570–1591

history of development of III – V compound semiconductor optical detectors. *Stillman, Gregory E., +, T-ED Nov 84* 1643–1655

Binary arithmetic; cf. Arithmetic**Bipolar integrated circuits**

double-diffused differential-amplification magnetic sensor with good magnetic sensitivity which can be easily fabricated with bipolar IC technology. *Huang, Rei-Min, +, T-ED Jul 84* 1001–1004

high-speed monolithic 8-, 10-, and 12-bit digital-to-analog converters produced on standard high-speed digital bipolar process without post-process trimming. *Saul, Peter, +, T-ED Feb 84* 196–202

InGaAs/InP heterojunction bipolar transistors for integrated logic circuits (Abstr.). *Choudhury, A. N. M. Masum, +, T-ED Dec 84* 1980

I²L/emitter function logic data interface designed in OXIL technology for VLSI. *Baumert, Robert J., +, T-ED Feb 84* 160–165

nearly ideal unguarded VSi₂ Schottky-barrier diodes for bipolar VLSI (Abstr.). *Drobny, V. F., +, T-ED Dec 84* 1977

Bipolar integrated circuits; cf. Bipolar transistors; Emitter-coupled logic; Integrated injection logic**Bipolar integrated circuits, analog**

analog technology that integrates bipolar, CMOS, and DMOS transistors on single chip for LSI. *Krishna, Surinder, +, T-ED Jan 84* 89–95

Bipolar transistor amplifiers; cf. Power bipolar transistor amplifiers**Bipolar transistor switches**

charge-control analysis of class E switching-mode tuned power amplifier with only one inductor and one capacitor in load network. *Kazimierczuk, Marian, T-ED Mar 84* 366–373

Bipolar transistor switches; cf. Power bipolar transistor switches**Bipolar transistors**

analysis of heavily doped bipolar transistor emitters with polycrystalline Si contacts. *Yu, Zhiping, +, T-ED Jun 84* 773–784

dc and switching characteristics for n-p-n GaAlAs – GaAs heterojunction bipolar transistors. *Kurata, Mamoru, +, T-ED Apr 84* 467–473

determination of emitter and base series resistances of bipolar transistors. *Ning, Tak H., +, T-ED Apr 84* 409–412

effect of graded layers and tunneling on performance of AlGaAs/GaAs heterojunction bipolar transistors. *Grinberg, Anatoly A., +, T-ED Dec 84* 1758–1765

emitter – bandgap grading effects on GaAlAs/GaAs heterojunction bipolar transistors (Abstr.). *Yoshida, J., +, T-ED Dec 84* 1979

GaAs/(Ga,Al)As heterojunction bipolar transistors with buried oxygen-implanted isolation layers (Abstr.). *Asbeck, P. M., +, T-ED Dec 84* 1979

integral-equation solution of minority-carrier transport problems in heavily doped semiconductors. *De Castro, Ercole, +, T-ED Jun 84* 785–792

limits of validity of conventional drift-diffusion equation analysis for modeling bipolar transistor structures containing submicrometer dimensions. *Park, Young-June, +, T-ED Dec 84* 1724–1730

low-temperature dependence of nonideal base current component in low-concentration emitter n-p-n Si transistors. *Gonzalez-Bris, Carlos, +, T-ED Oct 84* 1503–1505

mathematical proof of validity of reciprocity in one-dimensional bipolar transistors with arbitrary base parameters. *De Man, Hugo J., +, T-ED Dec 84* 1720–1723

measurement of lifetime of excess base stored charge of saturated bipolar transistor at high collector currents. *Kazimierczuk, Marian, T-ED Mar 84* 374–378

measurement of p-n product in heavily doped epitaxial emitters of bipolar transistors. *Possin, George E., +, T-ED Jan 84* 3–17

model for lateral junction contour of double-diffused Gaussian profiles; application to double-diffused MOSFETs and bipolar transistors. *Kasley, K. L., +, T-ED Sep 84* 1341–1343

open diffusion technique for Zn diffusion in InP; use in fabrication of InGaAsP/InP lateral p-n-p transistors. *Schmitt, Felix, +, T-ED Aug 84* 1083–1085

operating principles of bipolar transistor magnetic sensors. *Vinal, Albert W., +, T-ED Oct 84* 1486–1494

path to conception of junction transistor. *Shockley, William, T-ED Nov 84* 1523–1546

physics and modeling of heavily doped emitters. *del Alamo, Jesús A., +, T-ED Dec 84* 1878–1888

polysilicon emitter bipolar transistors fabrication; effect of surface treatment prior to polysilicon deposition. *Ashburn, Peter, +, T-ED Jul 84* 853–860

radiative recombination from base of AlGaAs/GaAs heterojunction bipolar transistor prepared by MBE (Abstr.). *Hayes, J. R., +, T-ED Dec 84* 1979–1980

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- saturation currents in small-geometry oxide-isolated and groove-isolated transistor structures. *Stevens, E. H.*, *T-ED Jan 84* 80–82
transition from bipolar to bulk-barrier transistor. *Mader, Hermann, +*, *T-ED Oct 84* 1447–1454
transport study in Si–silicide–Si. *Abdeshaah, Rahim, +*, *T-ED Dec 84* 1701–1708
- Bipolar transistors;** cf. Bipolar integrated circuits; Microwave bipolar transistors; Millimeter-wave bipolar transistors; Permeable base transistors; Phototransistors; Power bipolar transistors
- Breakdown;** cf. Avalanche breakdown; Second breakdown
- Bremsstrahlung**
hot-electron-induced photon and photocarrier generation of minority carriers in Si MOSFETs. *Tam, Simon, +*, *T-ED Sep 84* 1264–1273
- Buffer memories;** cf. Cache memories
- Buffers**
NDRO Josephson quantized loop memory cell with buffer gate. *Miyahara, Kazunori, +*, *T-ED Jul 84* 888–894
wideband buffer amplifier for amplifying fast pulses from high-impedance capacitive source fabricated using 3.5- μ m NMOS technology. *Rodriguez, B. A., +*, *T-ED Feb 84* 203–205
- C**
- Cache memories**
1-kbit GaAs static RAM with E/D direct-coupled FET logic. *Ino, Masayuki, +*, *T-ED Sep 84* 1139–1144
- Cadmium materials/devices;** cf. Specific topic
- Capacitance measurement**
electrical characterization of feature sizes and parasitic capacitances in short-channel MOSFETs using single test structure. *Vitanov, Petko, +*, *T-ED Jan 84* 96–100
- Capacitors**
capacitively coupled traveling-wave amplifier with improved power-handling capability. *Ayasli, Yalcin, +*, *T-ED Dec 84* 1937–1942
- Capacitors;** cf. MIS capacitors; MOS capacitors
- Carrier processes;** cf. Charge-carrier processes
- Cathode-ray tubes**
account of author's experience with Kaiser–Aiken thin tube and rated work by D. Gabor and J. D. McGee at Imperial College. *Marshall, F. John*, *T-ED Nov 84* 1608–1609
electron devices history (special Centennial issue). *T-ED Nov 84* 1521–1672
thin cathode-ray tube development. *Aiken, W. Ross*, *T-ED Nov 84* 1605–1608
- Cavity resonators;** cf. Laser resonators
- CCD;** cf. Charge-coupled devices
- Charge-carrier processes**
extension of Schaffter–Gummel algorithm to energy balance equation. *Tang, Ting-wei*, *T-ED Dec 84* 1912–1914
- Charge-carrier processes;** cf. Specific topic
- Charge-coupled devices**
analytical method for computing two-dimensional potential profile in buried-channel CCD with zero gate separation. *Lester, T. P., +*, *T-ED Jul 84* 999–1001
CCD-based technique for measuring interface trap density near band edges. *Madan, Sudhir K., +*, *T-ED Oct 84* 1509–1511
design and performance of low-noise charge-detection amplifier for virtual phase charge-coupled devices. *Hynecek, Jaroslav*, *T-ED Dec 84* 1713–1719
geometry dependence of dark current in CCDs. *Chen, John Y., +*, *T-ED Dec 84* 1914–1916
quasi-three-dimensionally charge-coupled circuit for performing charge packet differencing operation. *Fossum, Eric R., +*, *T-ED Dec 84* 1784–1789
shift in empty-channel potential with channel width and effective channel width of buried-channel MOSFETs. *Burkey, Bruce C., +*, *T-ED Apr 84* 423–429
small-signal charge transfer inefficiency of surface-channel CCD. *Penning de Vries, René G. M., +*, *T-ED Oct 84* 1454–1462
theory of operation of amorphous-silicon charge-coupled devices. *Naruke, Yasuo, +*, *T-ED Mar 84* 362–366
- Charge-coupled image sensors**
CCD color signal separation IC for single-chip color imagers with color filter arrays. *Watanabe, Takashi, +*, *T-ED Feb 84* 183–188
frame-interline transfer CCD imager with very low smear level. *Hori, Kenji, +*, *T-ED Jul 84* 904–909
interline CCD image sensor with antiblooming structure consisting of vertical overflow drain under photodiode. *Ishihara, Yasuo, +*, *T-ED Jan 84* 83–88
interline CCD image sensor with reduced image lag. *Teranishi, Nobukazu, +*, *T-ED Dec 84* 1829–1833
output structure for buried-channel CCD. *Schlig, Eugene S., +*, *T-ED Dec 84* 1907–1908
- Si photodetector with detecting dynamic range in visible spectrum of more than 10⁷; use in integrated CCD and self-scanned MOSFET linear arrays. *Chamberlain, Savvas G., +*, *T-ED Feb 84* 175–182
- Charge-injection devices**
charge-injection transistor based on real-space hot-electron transfer. *Luryi, Serge, +*, *T-ED Jun 84* 832–839
- Charge-injection image sensors**
ideal mode operation of InSb charge-injection device. *Wei, Ching-Yeu, +*, *T-ED Dec 84* 1773–1780
- Charge-transfer devices**
photon-counting sensor based on buried-channel charge transfer MOS structure and operated at voltages in above-breakdown regime. *Lester, T. P., +*, *T-ED Oct 84* 1420–1427
- Charge-transfer devices;** cf. Charge-coupled devices
- Charge-transfer filters**
charge-packet splitting in charge-domain filters to implement fractional multiplication. *Bencuya, Selim S., +*, *T-ED Oct 84* 1494–1501
- Charge-transfer image sensors**
analysis of charge-priming transfer efficiency in CPD image sensors. *Senda, Kohji, +*, *T-ED Sep 84* 1324–1328
analysis of n-p-n photodiodes in p-well charge priming device image sensors. *Senda, Kohji, +*, *T-ED Dec 84* 1873–1877
- Chemical transducers**
influence of different insulators on Pd-gate MIS hydrogen sensors. *Dobos, Karoly, +*, *T-ED Apr 84* 508–510
- CID;** cf. Charge-injection devices
- Circuit ...;** cf. Integrated-circuit ...
- Circuit noise;** cf. Amplifier noise; Integrated-circuit noise
- Circuit sensitivity analysis;** cf. Sensitivity analysis/optimization
- Circuits;** cf. Phase shifters
- CMOS integrated circuits**
devices and technologies for custom ICs (joint special issue with *IEEE Journal of Solid-State Circuits*, Feb 1984). *T-ED Feb 84* 137–269
FIPOS (full isolation by porous oxidized silicon) technology and its application to LSI. *Imai, Kazuo, +*, *T-ED Mar 84* 297–302
high-performance latchup-free CMOS (Abstr.). *Sangiorgi, E., +*, *T-ED Dec 84* 1967
hot-electron aging in p-channel MOSFETs for VLSI CMOS. *Radojcic, Riko*, *T-ED Dec 84* 1896–1898
integrated Si magnetic field sensor using magnetodiode principle. *Popović, Radivoje S., +*, *T-ED Mar 84* 286–291
latchup and image crosstalk suppression in CMOS circuits by internal gettering. *Anagnostopoulos, Constantine N., +*, *T-ED Feb 84* 225–231
latchup model for parasitic p-n-p-n path in bulk CMOS. *Fang, Robert Ching-Yuh, +*, *T-ED Jan 84* 113–120
latchup suppression in fine-dimension shallow p-well CMOS circuits. *Lewis, Alan G.*, *T-ED Oct 84* 1472–1481
latchup susceptibility of CMOS to alpha-particle upsets (Abstr.). *Larkins, W. T., +*, *T-ED Dec 84* 1966–1967
layout and bias considerations for preventing transiently triggered latchup in CMOS circuits. *Troutman, Ronald R., +*, *T-ED Mar 84* 315–321
method for determining test chip sample size to estimate electrical parameter distribution on integrated circuit wafer. *Suehle, John S., +*, *T-ED Feb 84* 257–264
modeling physical limits on junction scaling for CMOS; program for 1-D modeling, PROSIM II. *Fair, Richard B., +*, *T-ED Sep 84* 1180–1185
optimum ion implantation and rapid thermal annealing processes for B and BF₂ implanted source–drain junctions for submicrometer CMOS technology (Abstr.). *Vasudev, P. K., +*, *T-ED Dec 84* 1966
optimum p-channel isolation structure for CMOS. *Sugino, Michael, +*, *T-ED Dec 84* 1823–1829
quadrapole-well CMOS for VLSI. *Chen, John Yuan-Tai*, *T-ED Jul 84* 910–919
selective epitaxial growth for fabrication of CMOS integrated circuits. *Ippi, Alfred C., +*, *T-ED Dec 84* 1741–1748
sensitivity of SPICE simulations to input parameter variations. *Cassard, Janet M.*, *T-ED Feb 84* 264–269
study of latch-up phenomena in CMOS structures. *Hu, Genda J.*, *T-ED Jan 84* 62–67
submicrometer p-channel FET with n⁺ polysilicon gate for VLSI. *Cham, Kit M., +*, *T-ED Jul 84* 964–968
substrate resistance calculation for latchup modeling of CMOS. *Terrill, Kyle W., +*, *T-ED Sep 84* 1152–1155
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- Color TV; cf. TV**
- Communication switching**
- I²L/emitter function logic data interface designed in OXIL technology for VLSI. *Baumert, Robert J., + , T-ED Feb 84* 160–165
- Complementary MOS; cf. CMOS**
- Component reliability; cf. Integrated-circuit reliability; Semiconductor device reliability**
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- Contacts; cf. Ohmic contacts; Semiconductor device metallization**
- Counting circuits**
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- Couplers; cf. Optical couplers**
- Coupling; cf. Electromagnetic coupling**
- Crossed-field devices**
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- Cryogenic materials/devices**
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- Deuterium**
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- Dielectric materials/devices**
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- Dielectric materials/devices; cf. Capacitors**
- Dielectric measurements; cf. Capacitance measurement**
- Difference methods; cf. Finite-difference methods**
- Differential amplifiers**
- double-diffused differential-amplification magnetic sensor with good magnetic sensitivity which can be easily fabricated with bipolar IC technology. *Huang, Rei-Min, + , T-ED Jul 84* 1001–1004
- Diffusion processes; cf. Specific topic**
- Digital – analog conversion**
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- Digital arithmetic; cf. Arithmetic**
- Digital integrated circuits; cf. Bipolar integrated circuits; CMOS integrated circuits; FET integrated circuits; Integrated circuits; Logic arrays; MOS integrated circuits; Schottky-barrier FET logic circuits; Very high-speed integrated circuits; Very large-scale integration**
- Digital switching (communication systems); cf. Communication switching**
- Diode lasers; cf. Semiconductor lasers**
- Diodes; cf. Semiconductor diodes**
- Displays**
- history of thin-film transistors; development and use in TFT-addressed displays. *Brody, T. Peter, T-ED Nov 84* 1614–1628
- Displays; cf. Electroluminescent materials/devices; Plasma displays**
- Distortion**
- coupling effects in time domain for interconnecting bus in high-speed GaAs logic circuits. *Chilo, Jean, + , T-ED Mar 84* 347–352
- Distortion; cf. Crosstalk; Delay distortion**
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- Distribution functions; cf. Probability**
- Doping; cf. Semiconductor device doping**

E

- ECL; cf. Emitter-coupled logic**
- EEPROM (electrically erasable programmable ROM); cf. Read-only memories**
- EHF (30–300 GHz); cf. Millimeter-wave**
- Electric variables measurement; cf. Capacitance measurement; Integrated-circuit measurements; Resistance measurement; Semiconductor device measurements**
- Electrodes**
- temperature measurement of coated-particle cathode of spherical geometry using retarding field method. *Dallos, Andras, + , T-ED Mar 84* 379–381
- Electroluminescent materials/devices**
- evaluation of conventional and composite dielectrics for use in ac thin-film electroluminescent displays. *Tiku, Shiban K., + , T-ED Jan 84* 105–108
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- coupling effects in time domain for interconnecting bus in high-speed GaAs logic circuits. *Chilo, Jean, + , T-ED Mar 84* 347–352
- input/output coupling in reflection-type tapered gyrotron traveling-wave amplifier. *Lau, Y. Y., + , T-ED Mar 84* 337(347)
- Electromagnetic propagation, absorbing media; cf. Optical propagation, absorbing media**
- Electron-beam focusing**
- methods for gridded Pierce electron guns with periodic permanent magnet focusing. *True, Richard, T-ED Mar 84* 353–362

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Electron-beam scanning devices; cf. Cathode-ray tubes

Electron beams; cf. Gyrotrons

Electron carriers; cf. Charge-carrier processes

Electron emission

charge emission from interface states at Si grain boundaries by thermal emission and thermionic-field emission; theory. *De Groot, A. W.*, +, *T-ED Oct 84* 1365–1369

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methods for gridded Pierce electron guns with periodic permanent magnet focusing. *True, Richard*, *T-ED Mar 84* 353–362

Electron radiation effects; cf. Integrated-circuit fabrication; Semiconductor device fabrication; Semiconductor device radiation effects; Semiconductor/device radiation effects

Electron tubes; cf. Specific topic

Electronics industry

semiconductor industry in Japan; past and present. *Watanabe, Makoto*, *T-ED Nov 84* 1562–1570

Electrooptic materials/devices

beginnings of integrated optoelectronic circuits; personal recollections. *Yariv, Amnon*, *T-ED Nov 84* 1656–1661

optoelectronic heterodyne detection of high-frequency intensity modulation signals using GaAs photoconductive mixer. *Lum, Dennis K. W.*, +, *T-ED Dec 84* 1766–1768

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three-layer Se–SeTe–Se photoreceptor with high sensitivity in red and near-infrared region for use in electrophotographic printers. *Tateishi, Kazuyoshi*, +, *T-ED Jun 84* 793–796

Electrostatic recording; cf. Electrophotography

Emitter-coupled logic

subnanosecond 2000-gate array with ECL 100K compatibility. *Saito, Fumihiko*, +, *T-ED Feb 84* 139–143

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comparison of intrinsic gettering and epitaxial wafers with respect to soft error endurance and other characteristics of 64-Kbit dynamic RAM. *Iwai, Hiroshi*, +, *T-ED Sep 84* 1149–1151

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single crystal Ge p-i-n diode grown by molecular-beam epitaxy on Si substrate; infrared photodetector for fiber-optics communication up to 1.5- μm region. *Luryi, Serge*, +, *T-ED Sep 84* 1135–1139

surface-induced latchup in CMOS structures with and without epitaxial layer. *Takacs, Dezsoe*, +, *T-ED Mar 84* 279–286

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Excimer lasers; cf. Gas lasers, excimer; Noble-gas lasers, excimer

Extremely high frequency (30–300 GHz); cf. Millimeter-wave

F

Fabrication; cf. Integrated-circuit fabrication; Materials processing; Semiconductor device fabrication; Thick-film device fabrication

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FET amplifiers; cf. Microwave FET amplifiers; MOSFET amplifiers

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instabilities in MODFETs and MODFET circuits. *Duh, K. H.*, +, *T-ED Sep 84* 1345–1346

FET integrated circuits

(AlGa)As/GaAs/(AlGa)As selectively doped double-heterojunction FET with extremely high channel conductivity (Abstr.). *Inoue, K.*, +, *T-ED Dec 84* 1962–1963

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FET integrated circuits; cf. CMOS integrated circuits; FET switches; FETs; MOS integrated circuits; Schottky-barrier FET logic circuits

FET integrated circuits, analog; cf. CMOS integrated circuits, analog; Microwave FET integrated circuits; MOS integrated circuits, analog

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FET switches; cf. Power FET switches

FETs

drain bias dependence of frequency limit of GaAs FETs. *Lee, Soong Hak*, +, *T-ED Aug 84* 1068–1071

electronic phenomena based on multilayer epitaxy. *Gossard, Arthur C.*, *T-ED Nov 84* 1667–1672

extended charge control model and characterization of modulation-doped FETs. *Lee, Kwyro*, +, *T-ED Jan 84* 29–35. †

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- extended 'end' resistance measurement technique to determine series source and drain resistance of modulation-doped FET. *Lee, Kwyro, + , T-ED Oct 84* 1394–1398
- I* – *V* and *C* – *V* characteristics of Al-undoped AlGaAs/GaAs capacitors as function of temperature in 300 – 77 K range; MISFETs for operation at 77 K. *Drummond, Timothy J., + , T-ED Sep 84* 1164–1168
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- transient capless annealing of ion-implanted GaAs. *Clarke, R. Chris, + , T-ED Aug 84* 1077–1082
- FETs; cf. CMOSFETs; FET integrated circuits; JFETs; Microwave FETs; Millimeter-wave FETs; Power FETs; Schottky-barrier FETs
- Field-effect transistors; cf. FET ...**
- Films; cf. Dielectric films
- Filters; cf. Bandpass filters; Charge-transfer filters; Optical filters
- Finite-difference methods**
- finite-difference GaAs IMPATT diode simulations in 20 – 44 GHz range. *Mains, Richard K., + , T-ED Sep 84* 1273–1279
- heat source and temperature profile in silicon-on-insulator multilayer structure illuminated by incoherent light source. *Kyung Min, T-ED Dec 84* 1845–1851
- two-dimensional numerical simulation program for calculation of concentration profiles of diffused dopants in semiconductors. *Bonomo, Antonio, + , T-ED Dec 84* 1708–1713
- Finite-element methods**
- study of latch-up phenomena in CMOS structures. *Hu, Genda J., T-ED Jan 84* 62–67
- Focusing; cf. Electron-beam focusing

G

- Gallium materials/devices**
- dc magnetic field effects on AlGaAs/GaAs real space transfer heterojunction oscillator. *Coleman, Paul D., + , T-ED Sep 84* 1145–1148
- electron velocity – field characteristics of GaAs and In_{0.53}Ga_{0.47}As below Gunn effect threshold (Abstr.). *Haase, M. A., + , T-ED Dec 84* 1984–1985
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- Gallium materials/devices; cf. Specific topic**
- Gallium materials/lasers**
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- stripe geometry InP/InGaAsP lasers fabricated with deuteron bombardment. *Schwartz, B., + , T-ED Jun 84* 841–843
- Galvanomagnetism; cf. Hall effect**
- Gas-discharge displays; cf. Plasma displays**
- Gas lasers, excimer**
- thyatron operation using He for high-power high-repetition rate applications; use with excimer lasers. *Guha, Shekhar, + , T-ED Jul 84* 992–993
- Gas lasers, excimer; cf. Noble-gas lasers, excimer
- Gas switches; cf. Thyatron**
- Geometry**
- geometry dependence of dark current in CCDs. *Chen, John Y., + , T-ED Dec 84* 1914–1916
- optimization of on-resistance in vertical DMOS power FETs with linear and hexagonal surface geometries. *Board, Kenneth, + , T-ED Jan 84* 75–80
- Germanium materials/devices; cf. Specific topic**
- Gunn device oscillators**
- dc magnetic field effects on AlGaAs/GaAs real space transfer heterojunction oscillator. *Coleman, Paul D., + , T-ED Sep 84* 1145–1148
- Gunn devices**
- electron velocity – field characteristics of GaAs and In_{0.53}Ga_{0.47}As below Gunn effect threshold (Abstr.). *Haase, M. A., + , T-ED Dec 84* 1984–1985
- Gyrotrons**
- input/output coupling in reflection-type tapered gyrotron traveling-wave amplifier. *Lau, Y. Y., + , T-ED Mar 84* 337 (347)
- large-signal theory of two-stage tapered gyro-TWT. *Ganguly, Achintya K., + , T-ED Apr 84* 474–480
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- theory of high-harmonic rectangular gyrotron for TE_{mn} modes. *Ferenczi, Altan M., + , T-ED Sep 84* 1212–1218
- unified theory of diocotron, cyclotron maser, and negative-mass instabilities. *Lau, Y. Y., T-ED Mar 84* 329–337

H

- Hall effect**
- electronic phenomena based on multilayer epitaxy. *Gossard, Arthur C., T-ED Nov 84* 1667–1672
- Heterodyning**
- optoelectronic heterodyne detection of high-frequency intensity modulation signals using GaAs photoconductive mixer. *Lam, Dennis K. W., + , T-ED Dec 84* 1766–1768
- Heterojunctions; cf. Semiconductor heterojunctions**
- Hierarchical systems**
- 1.2- μm double-level-metal CMOS process and associated gate array and semicustom design approaches. *Preckshot, Nancy E., + , T-ED Feb 84* 215–225
- History**
- account of author's experience with Kaiser – Aiken thin tube and related work by D. Gabor and J. D. McGee at Imperial College. *Marshall, F. John, T-ED Nov 84* 1608–1609
- account of early conceptual stages and development of one-device MOSFET dynamic RAM. *Dennard, Robert H., T-ED Nov 84* 1549–1555
- account of personal involvement with electron tubes from 1920s to present. *Preist, Donald H., T-ED Nov 84* 1609–1611
- account of personal magnetron development activities at General Electrical Research Laboratory during World War II. *Hull, Joseph F., T-ED Nov 84* 1611–1613
- (AlGa)As/GaAs double-heterostructure laser development. *Hayashi, Izuo, T-ED Nov 84* 1630–1642
- beginnings of integrated optoelectronic circuits; personal recollections. *Yariv, Amnon, T-ED Nov 84* 1656–1661
- development of selectively doped heterostructure transistor; personal recollections. *Dingle, Raymond, T-ED Nov 84* 1662–1667
- electron devices history (special Centennial issue). *T-ED Nov 84* 1521–1672
- evolution of power device technology. *Adler, Michael S., + , T-ED Nov 84* 1570–1591
- historical account of early Si crystal-growing experience at General Electric; growth of oxygen-free Si. *Thomas, Robert C., T-ED Nov 84* 1547–1549
- history of development of III – V compound semiconductor optical detectors. *Stillman, Gregory E., + , T-ED Nov 84* 1643–1655
- history of thin-film transistors; development and use in TFT-addressed displays. *Brody, T. Peter, T-ED Nov 84* 1614–1628
- magnetron and crossed-field device development from World War II years to present. *Brown, William C., T-ED Nov 84* 1595–1605
- magnetron development work in years 1929 to 1938. *Kilgore, G. Ross, T-ED Nov 84* 1593–1595
- path to conception of junction transistor. *Shockley, William, T-ED Nov 84* 1523–1546
- semiconductor industry in Japan; past and present. *Watanabe, Makoto, T-ED Nov 84* 1562–1570
- thin cathode-ray tube development. *Aiken, W. Ross, T-ED Nov 84* 1605–1608
- Hole carriers; cf. Charge-carrier processes**
- Hybrid integrated circuits**
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IGFETs

high-field electron capture and emission in nitrided silicon dioxide (Abstr.). *Terry, F. L., Jr.*, +, *T-ED Dec 84* 1971–1972

Image sensors

latch-up and image crosstalk suppression in CMOS circuits by internal gettering. *Anagnostopoulos, Constantine N.*, +, *T-ED Feb 84* 225–231

Si photodetector with detecting dynamic range in visible spectrum of more than 10⁷; use in integrated CCD and self-scanned MOSFET linear arrays. *Chamberlain, Savvas G.*, +, *T-ED Feb 84* 175–182

Image sensors; cf. Charge-injection image sensors; Charge-transfer image sensors; Infrared image sensors; TV image sensors**IMPATT diode oscillators**

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finite-difference GaAs IMPATT diode simulations in 20 – 44 GHz range. *Mains, Richard K.*, +, *T-ED Sep 84* 1273–1279

high-power multimesa GaAs hybrid double-drift IMPATTs for pulsed operation at X-band. *Vasudev, Prahad K.*, *T-ED Aug 84* 1044–1050

IMPATT diodes

effects of transient carrier transport in millimeter-wave GaAs diodes. *Grondin, R. O.*, +, *T-ED Jan 84* 21–28

multiple-wafer vapor-phase epitaxial system for uniform deposition of GaAs; growth of IMPATT material. *Lau, Kei May*, +, *T-ED Aug 84* 1086–1089

Indium materials/devices; cf. Specific topic**Inductive transducers; cf. Magnetic transducers****Infrared amplifiers**

heterojunction phototransistor with double heterojunction LED integrated onto collector which exhibits light amplification, optical bistability, light-activated switching, and unidirectionality. *Sasaki, Akio*, +, *T-ED Jun 84* 805–811

Infrared detectors

enhanced quantum efficiency of Pd₂Si Schottky infrared diodes on <111> Si. *McKee, Richard*, *T-ED Jul 84* 968–970

high-gain InGaAsP/InP heterojunction phototransistors with narrow spectral response fabricated by applying InGaAsP absorption layer to emitter surface. *Mitsuyu, Tsuneo*, +, *T-ED Jun 84* 812–817

three-layer Se – SeTe – Se photoreceptor with high sensitivity in red and near-infrared region for use in electrophotographic printers. *Tateishi, Kazuyoshi*, +, *T-ED Jun 84* 793–796

Infrared detectors; cf. Optical fiber receivers**Infrared image sensors**

ideal mode operation of InSb charge-injection device. *Wei, Ching-Yeu*, +, *T-ED Dec 84* 1773–1780

Infrared lasers

single-quantum-well PbEuSeTe diode lasers; CW operation up to 174 K (at 4.41 μm) and pulsed operation up to 241 K (at 4.01 μm) (Abstr.). *Partin, D. L.*, *T-ED Dec 84* 1975

Infrared lasers; cf. Optical fiber transmitters, lasers**Infrared modulation/demodulation; cf. Optical fiber transmitters****Infrared receivers; cf. Optical fiber receivers****Infrared (0.70 – 100 μm); cf. Submillimeter-wave (300 – 3000 GHz)****Injection lasers; cf. Semiconductor lasers****Innovation; cf. Technological innovation****Integral equations**

integral-equation solution of minority-carrier transport problems in heavily doped semiconductors. *De Castro, Ercole*, +, *T-ED Jul 84* 785–792

Integrated-circuit design; cf. Layout, integrated circuits**Integrated-circuit doping**

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Integrated-circuit doping; cf. Integrated-circuit ion implantation**Integrated-circuit fabrication**

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improved sidewall masked isolation process for VLSI (Abstr.). *Teng, Clarence W.*, +, *T-ED Dec 84* 1966

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reciprocity behavior of photoresists in excimer laser lithography. *Rice, Sondra*, +, *T-ED Jan 84* 1–3

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transient capless annealing of ion-implanted GaAs. *Clarke, R. Chris*, +, *T-ED Aug 84* 1077–1082

Integrated-circuit fabrication; cf. Epitaxial growth; Integrated-circuit doping; Integrated-circuit ion implantation; Integrated-circuit metallization; Layout, integrated circuits; Specific topic

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analysis of crosstalk in very-high-speed LSI/VLSI using multiconductor MIS microstrip line model. *Seki, Shouhei*, +, *T-ED Dec 84* 1498–1503

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MoSi₂/thin poly-Si gate process technology without dielectric degradation of gate oxide. *Fukumoto, Masanori*, +, *T-ED Oct 84* 1432–1439

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Integrated-circuit interconnections; cf. Aluminum conductors, integrated circuits; Layout, integrated circuits

Integrated-circuit ion implantation

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low-resistance MOS technology using self-aligned refractory silicidation. *Okabayashi, Hidekazu*, +, *T-ED Sep 84* 1329–1334

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uniformity evaluation of MESFETs for GaAs LSI. *Matsuoka, Yutaka*, +, *T-ED Aug 84* 1062–1067

Integrated-circuit measurements; cf. Integrated-circuit testing

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low-resistance MOS technology using self-aligned refractory silicidation. *Okabayashi, Hidekazu*, +, *T-ED Sep 84* 1329–1334

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Integrated-circuit metallization; cf. Aluminum conductors, integrated circuits; Integrated-circuit interconnections

Integrated-circuit noise

noise associated with distributed resistance of MOSFET gate structures in integrated circuits. *Jindal, R. P.*, *T-ED Oct 84* 1505–1509

Integrated-circuit radiation effects

capacitance coupling memory cell for VLSI which offers small cell area, readout signal gain, and high alpha-particle immunity. *Terada, Kazuo*, +, *T-ED Sep 84* 1319–1324

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Integrated circuits; cf. Bipolar integrated circuits; CMOS integrated circuits; FET integrated circuits; Hybrid integrated circuits; Integrated optics; Josephson devices; Large-scale integration; MOS integrated circuits; Very high-speed integrated circuits; Very large-scale integration

Integrated circuits industry; cf. Electronics industry

Integrated injection logic

I²L/emitter function logic data interface designed in OXIL technology for VLSI. *Baumert, Robert J., +, T-ED Feb 84* 160–165

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Integrated optics

beginnings of integrated optoelectronic circuits; personal recollections. *Yariv, Amnon, T-ED Nov 84* 1656–1661

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Interconnection networks; cf. Communication switching

Interconnections, integrated circuits; cf. Integrated-circuit interconnections; Layout, integrated circuits

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Interpolation; cf. Digital – analog conversion

Ion implantation; cf. Integrated-circuit ion implantation; Semiconductor device ion implantation

Ion radiation effects

preparation of clean GaAs(100) surface by Ar argon ion bombardment. *Sinharoy, Samar, +, T-ED Aug 84* 1090–1092

Ion radiation effects; cf. Semiconductor device fabrication

I²L; cf. Integrated injection logic

J**Japan**

semiconductor industry in Japan; past and present. *Watanabe, Makoto, T-ED Nov 84* 1562–1570

JFET integrated circuits; cf. JFETs

JFET integrated circuits, analog

micropower monolithic filters realized using bipolar-compatible JFET technology; switched-capacitor and continuous analog filters. *Parpia, Zahir, +, T-ED Feb 84* 165–171

JFETs

breakdown phenomena in Si n-type JFET. *Sakai, Tatsuo, +, T-ED Jul 84* 873–879

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high-speed two-bit dual rail adder using asymmetrical interference device Josephson logic gate. *Yamada, Hajime, +, T-ED Mar 84* 307–310

wide-margin Josephson adder employing high-grain direct-coupled logic gate. *Hokkawa, Kohji, +, T-ED Jul 84* 983–987

Josephson device memories

NDRO Josephson quantized loop memory cell with buffer gate. *Miyahara, Kazunori, +, T-ED Jul 84* 888–894

nondestructive readout RAM utilizing two-dimensional array of single-quantum vortices in thin-film type-II superconductor. *Parisi, Jürgen, +, T-ED Mar 84* 310–314

Junction FETs; cf. JFETs

Junction lasers; cf. Semiconductor lasers

Junctions; cf. Semiconductor junctions

K**Klystrons**

account of personal involvement with electron tubes from 1920s to present. *Preist, Donald H., T-ED Nov 84* 1609–1611

L**Large-scale integration; cf.** Specific topic; Very large-scale integration

Laser applications; cf. Optical fiber transmitters, lasers

Laser applications, materials processing; cf. Integrated-circuit fabrication; Semiconductor device fabrication

Laser applications, measurement

nondestructive measurement of solar cell sheet resistance using laser scanner. *Kowalski, Paul, +, T-ED May 84* 566–570

Laser-beam effects; cf. Laser radiation effects

Laser cavity resonators; cf. Laser resonators

Laser diodes; cf. Semiconductor lasers

Laser measurement; cf. Laser applications, measurement

Laser radiation effects

microwave oscillators and optical effects from resonant tunneling quantum well structures (Abstr.). *Sollner, T. C. L. G., +, T-ED Dec 84* 1985

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high-energy ($\lambda \leq 7300 \text{ \AA}$) 300-K operation of single- and multiple-stripe quantum-well heterostructure laser diodes in external grating cavity (Abstr.). *Epler, J. E., +, T-ED Dec 84* 1974–1975

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Lasers; cf. CW lasers; Distributed-feedback lasers; Gas lasers; Pulsed lasers; Semiconductor lasers

Lateral devices

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Layout

- optimum design of power MOSFETs. *Hu, Chenming, +, T-ED Dec 84* 1693–1700

Layout, integrated circuits

- layout and bias considerations for preventing transiently triggered latchup in CMOS circuits. *Troutman, Ronald R., +, T-ED Mar 84* 315–321
- noise associated with distributed resistance of MOSFET gate structures in integrated circuits. *Jindal, R. P., T-ED Oct 84* 1505–1509

Light-activated switches; cf. Light-triggered switches

Light-triggered switches

- heterojunction phototransistor with double heterojunction LED integrated onto collector which exhibits light amplification, optical bistability, light-activated switching, and unidirectionality. *Sasaki, Akio, +, T-ED Jun 84* 805–811

Logic arrays

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Logic circuits; cf. Addition; Bipolar integrated circuits; CMOS integrated circuits; Emitter-coupled logic; FET integrated circuits; Integrated injection logic; Josephson device logic; Logic arrays; MCS integrated circuits; Schottky-barrier FET logic circuits

Logic devices; cf. Josephson device logic

LSI; cf. Large-scale integration

Luminescent materials/devices; cf. Electroluminescent materials/devices

M

Magnetic-field effects; cf. Specific topic

Magnetic logic devices; cf. Josephson device logic

Magnetic materials/devices; cf. Integrated magnetic devices

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- two-dimensional numerical analysis of Si magnetic field sensor. *Baltes, Henry P., +, T-ED Jul 84* 996–999

Magnetrons

- account of personal involvement with electron tubes from 1920s to present. *Preist, Donald H., T-ED Nov 84* 1609–1611

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Magnets; cf. Permanent magnets

Materials processing

- preparation of clean GaAs(100) surface by Ar argon ion bombardment. *Sinharoy, Samar, +, T-ED Aug 84* 1090–1092

Measurement; cf. Integrated-circuit measurements; Laser applications measurement; Semiconductor device measurements

Memories; cf. Cache memories; Josephson device memories; NDRC memories; Random-access memories; Read-only memories

Mercury materials/devices; cf. Specific topic

MESFETs; cf. Microwave FETs; Millimeter-wave FETs; Schottky-barrier FETs

Metal-insulator-semiconductor; cf. MIS ...

Metal-oxide-semiconductor; cf. MOS ...

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Metal-semiconductor devices; cf. Schottky-barrier devices

Metallization; cf. Integrated-circuit metallization; Semiconductor device metallization

Microstrip

- analysis of crosstalk in very-high-speed LSI/VLSI using multiconductor MIS microstrip line model. *Seki, Shouhei, +, T-ED Dec 84* 1498–1503

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Microwave FET integrated circuits; cf. Microwave FET amplifiers

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- collapse of drain $I-V$ characteristics of modulation-doped field-effect transistors at cryogenic temperatures. *Fischer, Russell J., +, T-ED Aug 84* 1028–1032

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Microwave generation; cf. Microwave oscillators

Microwave integrated circuits; cf. Microwave FET integrated circuits

Microwave oscillators

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Microwave oscillators; cf. Magnetrons

Microwave phase shifters; cf. Phase shifters

Microwave transistors; cf. Microwave bipolar transistors; Microwave FETs

Microwave (3–30 GHz); cf. Millimeter-wave (30–300 GHz)

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- Millimeter-wave amplifiers**
input/output coupling in reflection-type tapered gyrotron traveling-wave amplifier. *Lau, Y. Y.*, +, *T-ED Mar 84* 337 (347)
- Millimeter-wave bipolar transistors**
modeling of AlGaAs/GaAs heterostructure bipolar transistors by 2-D computer simulation. *Yokoyama, Kiyoyuki*, +, *T-ED Sep 84* 1222–1229
- Millimeter-wave diodes**
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- Millimeter-wave diodes; cf. IMPATT diodes; Millimeter-wave mixers**
- Millimeter-wave FETs**
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- Millimeter-wave frequency conversion; cf. Millimeter-wave mixers**
- Millimeter-wave generation; cf. Millimeter-wave oscillators**
- Millimeter-wave mixers**
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- Millimeter-wave oscillators**
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- Millimeter-wave transistors; cf. Millimeter-wave bipolar transistors; Millimeter-wave FETs**
- Millimeter-wave (30 – 300 GHz); cf. Microwave (3 – 30 GHz); Submillimeter-wave (300 – 3000 GHz)**
- MIS capacitors**
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- MIS capacitors; cf. MOS capacitors**
- MIS devices**
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modeling of grain boundary effects on photovoltaic properties of metal-insulator thin-film polycrystalline semiconductor solar cells. *So, S. M.*, +, *T-ED May 84* 696–707
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long-term retention of SNOS nonvolatile memory devices. *Topich, James A.*, *T-ED Dec 84* 1908–1910
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limits of validity of conventional drift-diffusion equation analysis for modeling bipolar transistor structures containing submicrometer dimensions. *Park, Young-June*, +, *T-ED Dec 84* 1724–1730
mark detection technology in electron-beam direct writing. *Kashiwaki, Tadashi*, +, *T-ED Oct 84* 1403–1407
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transport study in Si – silicide – Si. *Abdeshaah, Rahim*, +, *T-ED Dec 84* 1701–1708
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recombination lifetime measurement using pulsed MOS capacitor. *Schroder, Dieter K.*, +, *T-ED Apr 84* 462–467
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measurement of electron tunneling, oxide hole transport, and hot-electron impact ionization currents in bistable metal – tunnel oxide – semiconductor junctions. *Fossum, Eric R.*, +, *T-ED Sep 84* 1168–1174
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CASTAM process variation analysis simulator for MOS LSI. *Aoki, Yukio*, +, *T-ED Oct 84* 1462–1467
effect of high fields on MOS device and circuit performance. *Sodini, Charles G.*, +, *T-ED Oct 84* 1386–1393
electrical characterization of feature sizes and parasitic capacitances in short-channel MOSFETs using single test structure. *Vitanov, Petko*, +, *T-ED Jan 84* 96–100
electromigration lifetime studies of submicrometer-linewidth Al – Cu conductors. *Iyer, Subramanian S.*, +, *T-ED Oct 84* 1468–1471
field isolation technology using lift-off patterning of sputtered SiO_2 films. *Yachi, Toshiaki*, +, *T-ED Dec 84* 1748–1752
low-resistance MOS technology using self-aligned refractory silicidation. *Okabayashi, Hidekazu*, +, *T-ED Sep 84* 1329–1334
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selective epitaxial growth isolation for small-geometry MOS VLSI. *Endo, Nobuhiro*, +, *T-ED Sep 84* 1283–1288
tungsten gate process for use in MOS VLSI. *Iwata, Seichi*, +, *T-ED Sep 84* 1174–1179
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analog technology that integrates bipolar, CMOS, and DMOS transistors on single chip for LSI. *Krishna, Surinder*, +, *T-ED Jan 84* 89–95
model for finite small-signal drain – body and source – body conductances in MOSFETs associated with junction diffusion leakage currents. *Shoucar, F. S.*, +, *T-ED Dec 84* 1866–1872
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account of early conceptual stages and development of one-device MOSFET dynamic RAM. *Dennard, Robert H.*, *T-ED Nov 84* 1549–1555
capacitance coupling memory cell for VLSI which offers small cell area, readout signal gain, and high alpha-particle immunity. *Terada, Kazuo*, +, *T-ED Sep 84* 1319–1324
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threshold voltage instability of MOSFETs in MOS static RAM under accelerated operating test conditions at 77 K. *Watanabe, Yoshio*, *T-ED Dec 84* 1898–1901
50-ns 15-V alterable nonvolatile memory; operational model. *Horiuchi, Masatada*, +, *T-ED Jun 84* 739–746
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- MOSFET amplifiers**
design and performance of low-noise charge-detection amplifier for virtual phase charge-coupled devices. *Hynecek, Jaroslave*, *T-ED Dec 84* 1713–1719
wideband buffer amplifier for amplifying fast pulses from high-impedance capacitive source fabricated using 3.5- μm NMOS technology. *Rodriguez, B. A.*, +, *T-ED Feb 84* 203–205
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Si photodetector with detecting dynamic range in visible spectrum of more than 10⁷; use in integrated CCD and self-scanned MOSFET linear arrays. *Chamberlain, Savvas G.*, +, *T-ED Feb 84* 175–182
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- MOSFET switches; cf. Power FET switches**
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ac measurement technique to accurately determine MOSFET constants. *Thoma, Morgan J.*, +, *T-ED Sep 84* 1113–1116
accuracy of effective channel length/external resistance extraction algorithm for MOSFETs. *Laux, Steven E.*, *T-ED Sep 84* 1245–1251
analytical model for threshold voltage of narrow-width MOSFET. *Cheng, Y. C.*, +, *T-ED Dec 84* 1814–1823
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 cascode connected field-effect transistor (CASFET) with very low input capacitance that combines short-gate MOSFET with long-channel JFET. *Jackel, Lawrence D.*, +, *T-ED Dec 84* 1752–1758
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 experimental determination of saturation point of MOSFET. *Booth, Richard V. H.*, +, *T-ED Feb 84* 247–251
 fabrication of self-aligned Al-gate MOSFETs by Al pattern formation process using substitution reaction of Al for polysilicon. *Fujieda, Yukio*, +, *T-ED Jun 84* 828–832
 generalized scaling theory and its application to 0.25-μm MOSFET design. *Baccarani, Giorgio*, +, *T-ED Apr 84* 452–462
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 MOSFET degradation due to stressing of thin oxide. *Liang, Mong-Song*, +, *T-ED Sep 84* 1238–1244
 MOSFETs fabricated in laser-recrystallized Si on quartz using selectively absorbing dielectric layers. *Possin, George E.*, +, *T-ED Jan 84* 68–74
 nonuniform displacement of MOSFET channel pinchoff. *Chamberlain, Savvas G.*, +, *T-ED Feb 84* 252–256
 optimization of breakdown voltage and on-resistance of VDMOS transistors. *Darwish, Mohamed N.*, +, *T-ED Dec 84* 1769–1773
 parametric short-channel MOS transistor model for subthreshold and strong inversion current. *Grotjohn, Tim*, +, *T-ED Feb 84* 234–246
 physical correspondence between MOS and metal/AlGaAs/GaAs modulation-doped structures. *Pierret, R. F.*, +, *T-ED Mar 84* 383–385
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 use of focused ion beams for both implantation and gate lithography in Si MOSFET fabrication. *Kubena, Randall L.*, +, *T-ED Sep 84* 1186–1189
 MOSFETs; cf. CMOSFETs; MOS integrated circuits; Power FETs
 Multilevel systems; cf. Hierarchical systems
 Multiplication
 charge-packet splitting in charge-domain filters to implement fractional multiplication. *Bencuya, Selim S.*, +, *T-ED Oct 84* 1494–1501

N

NDRO memories

NDRO Josephson quantized loop memory cell with buffer gate. *Miyahara, Kazunori*, +, *T-ED Jul 84* 888–894
 nondestructive readout RAM utilizing two-dimensional array of single-quantum vortices in thin-film type-II superconductor. *Parisi, Jürgen*, +, *T-ED Mar 84* 310–314

Negative-resistance devices

light detector based on negative resistance characteristic of phototransistor-type optocoupler. *Takahashi, Haruo*, +, *T-ED Jul 84* 951–954
 measurement of electron tunneling, oxide hole transport, and hot-electron impact ionization currents in bistable metal – tunnel oxide – semiconductor junctions. *Fossum, Eric R.*, +, *T-ED Sep 84* 1168–1174
 negative differential resistance in quantum-state transfer superlattice diodes (Abstr.). *Kirchoefer, S. W.*, +, *T-ED Dec 84* 1985

Noble-gas lasers, excimer

reciprocity behavior of photoresists in excimer laser lithography. *Rice, Sondra*, +, *T-ED Jan 84* 1–3

Noise; cf. Amplifier noise; Integrated-circuit noise; Phase noise; Semiconductor device noise

Noncrystalline semiconductor materials/devices; cf. Amorphous semiconductor materials/devices

Nondestructive readout memories; cf. NDRO memories

Nonlinear oscillators; cf. Oscillators

Numerical methods

two-dimensional numerical analysis of Si magnetic field sensor. *Baltes, Henry P.*, +, *T-ED Jul 84* 996–999

Numerical methods; cf. Arithmetic; Finite-difference methods; Finite-element methods; Monte Carlo methods

O

Ohmic contacts

hot-plate alloying for ohmic contacts to GaAs; application to high-throughput automatic processing. *Henry, H. George*, +, *T-ED Aug 84* 1100–1103

overview of ohmic contacts on solar cells. *Schroder, Dieter K.*, +, *T-ED May 84* 637–647

Optical ...; cf. Infrared ...

Optical amplifiers

optically controlled amorphous Si photosensitive device. *Maruska, H. Paul*, +, *T-ED Sep 84* 1343–1345

Optical amplifiers; cf. Infrared amplifiers

Optical bistability

heterojunction phototransistor with double heterojunction LED integrated onto collector which exhibits light amplification, optical bistability, light-activated switching, and unidirectionality. *Sasaki, Akio*, +, *T-ED Jun 84* 805–811

Optical couplers

light detector based on negative resistance characteristic of phototransistor-type optocoupler. *Takahashi, Haruo*, +, *T-ED Jul 84* 951–954

Optical detectors

light detector based on negative resistance characteristic of phototransistor-type optocoupler. *Takahashi, Haruo*, +, *T-ED Jul 84* 951–954

Optical detectors; cf. Infrared detectors; Photodetectors

Optical fiber receivers

Ge reachthrough avalanche photodiodes for optical communication systems at 1.55-μm region. *Mikawa, Takashi*, +, *T-ED Jul 84* 971–977

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- (AlGa)As/GaAs double-heterostructure laser development. *Hayashi, Izuo*, *T-ED Nov 84* 1630–1642
- Optical fiber transmitters, lasers**
- 14-GHz operation of Q-switched diode lasers (Abstr.). *Tsang, Z.*, +, *T-ED Dec 84* 1973–1974
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- CCD color signal separation IC for single-chip color imagers with color filter arrays. *Watanabe, Takashi*, +, *T-ED Feb 84* 183–188
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- Optical measurements; cf. Laser applications, measurement**
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- optoelectronic heterodyne detection of high-frequency intensity modulation signals using GaAs photoconductive mixer. *Lam, Dennis K. W.*, +, *T-ED Dec 84* 1766–1768
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- Optical modulation/demodulation; cf. Optical mixers**
- Optical propagation, absorbing media**
- optical absorption of thin films deposited on Lambertian reflector substrate. *Sheng, Ping*, *T-ED May 84* 634–636
- Optical radiation effects; cf. Integrated-circuit fabrication; Laser radiation effects; Semiconductor device fabrication; Semiconductor device radiation effects; Ultraviolet radiation effects**
- Optical resonators; cf. Laser resonators**
- Optical signal processing; cf. Optical filters**
- Optical strip waveguides**
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- photon-counting sensor based on buried-channel charge transfer MOS structure and operated at voltages in above-breakdown regime. *Lester, T. P.*, +, *T-ED Oct 84* 1420–1427
- Optical transmitters; cf. Optical fiber transmitters**
- Optical waveguides; cf. Optical strip waveguides**
- Optimization methods; cf. Layout**
- Oscillators**
- dc magnetic field effects on AlGaAs/GaAs real space transfer heterojunction oscillator. *Coleman, Paul D.*, +, *T-ED Sep 84* 1145–1148
 - GaAs MESFET ring oscillator on Si substrate (Abstr.). *Ishida, T.*, +, *T-ED Dec 84* 1988
- Oscillators; cf. Gunn device oscillators; Microwave oscillators; Millimeter-wave oscillators**
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- P**
- p-i-n diodes**
- gated V-groove p-i-n diode static induction thyristor. *Fisher, Carole A.*, +, *T-ED Sep 84* 1299–1308
 - role of B profiling in enhancing performance of amorphous-Si-based p-i-n solar cells. *Hack, Michael*, +, *T-ED May 84* 539–542
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- lateral p-i-n photodetector fabricated on semi-insulating InGaAs and InP (Abstr.). *Diadiuk, V.*, +, *T-ED Dec 84* 1973
- p-i-n photodiodes; cf. Optical fiber receivers**
- Packaging; cf. Semiconductor device packaging**
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- method for determining test chip sample size to estimate electrical parameter distribution on integrated circuit wafer. *Suehle, John S.*, +, *T-ED Feb 84* 257–264
- Permanent magnets**
- methods for gridded Pierce electron guns with periodic permanent magnet focusing. *True, Richard*, *T-ED Mar 84* 353–362
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- GaAs permeable base transistors fabricated using organometallic chemical vapor deposition (Abstr.). *Nichols, Kirby B.*, +, *T-ED Dec 84* 1969–1970
 - low-frequency noise in permeable base transistors. *Zhu, Xichen C.*, +, *T-ED Oct 84* 1408–1413
- Phase distortion; cf. Delay distortion**
- Phase noise**
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- wideband monolithic phase shifter operating in 2 – 8-GHz frequency range. *Ayasl, Yalcin*, +, *T-ED Dec 84* 1943–1947
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- independence of mobility from surface conditions in InP:Fe fast photoconductivity devices due to Dember effect. *Hwang, Bor-Yuan*, +, *T-ED Jan 84* 101–104
 - optoelectronic heterodyne detection of high-frequency intensity modulation signals using GaAs photoconductive mixer. *Lam, Dennis K. W.*, +, *T-ED Dec 84* 1766–1768
- Photodetectors**
- Si photodetector with detecting dynamic range in visible spectrum of more than 10⁷; use in integrated CCD and self-scanned MOSFET linear arrays. *Chamberlain, Savvas G.*, +, *T-ED Feb 84* 175–182
- Photodetectors; cf. Infrared detectors; Photoconducting materials/devices; Photodiodes; Phototransistors**
- Photodiodes**
- analysis of n-p-n photodiodes in p-well charge priming device image sensors. *Senda, Kohji*, +, *T-ED Dec 84* 1873–1877
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 - photodiode quantum efficiency improvement and spectral response alteration through surface effects in vacuum. *Kopeika, N. S.*, +, *T-ED Sep 84* 1198–1206
 - physics and modeling of heavily doped emitters. *del Alamo, Jesús A.*, +, *T-ED Dec 84* 1878–1888
 - spectral response of n⁺-n-p and n⁺-p photodiodes. *Arora, Narain D.*, +, *T-ED Apr 84* 430–434
- Photodiodes; cf. Avalanche photodiodes; Optical fiber receivers; p-i-n photodiodes**
- Phototransistors**
- high-gain InGaAsP/InP heterojunction phototransistors with narrow spectral response fabricated by applying InGaAsP absorption layer to emitter surface. *Mitsuyu, Tsuneo*, +, *T-ED Jun 84* 812–817
 - light detector based on negative resistance characteristic of phototransistor-type optocoupler. *Takahashi, Haruo*, +, *T-ED Jul 84* 951–954
- Photovoltaic power cell doping**
- role of B profiling in enhancing performance of amorphous-Si-based p-i-n solar cells. *Hack, Michael*, +, *T-ED May 84* 539–542
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- high-efficiency ion-implanted Si solar cells. *Spitzer, Mark B.*, +, *T-ED May 84* 546–550
- Photovoltaic power cell materials**
- CdTe thin films for solar cell applications deposited by close-spaced vapor transport and by hot-wall vacuum evaporation. *Bube, Richard H.*, +, *T-ED May 84* 528–538
 - dominant grain structure in edge-supported pulling Si sheets studied by electron channeling and electron-beam-induced current measurements. *Tsuo, Y. S.*, +, *T-ED May 84* 614–618
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- Photovoltaic power cell measurements**
- contact resistance in solar cell; measurement and relative importance to power loss. *Meier, Daniel L.*, +, *T-ED May 84* 647–653
 - direct measurement of solar cell shunt resistance. *Chan, Daniel S. H.*, +, *T-ED Mar 84* 381–383
 - measurement of minority-carrier diffusion length and surface recombination velocity in thin semiconductor layers. *Gonzalez, Franklin N.*, +, *T-ED Apr 84* 413–416
 - minority-carrier lifetime measurements on Si solar cells using I_{sc} and V_{oc} transient decay. *Rose, B. H.*, *T-ED May 84* 559–565
 - nondestructive measurement of solar cell sheet resistance using laser scanner. *Kowalski, Paul*, +, *T-ED May 84* 566–570
 - series resistance determination for solar cells from I – V measurements under high illumination. *Phang, Jacob C. H.*, +, *T-ED May 84* 717–718
 - unifying view of transient responses for determining lifetime and surface recombination velocity in Si diodes and back-surface-field solar cells. *Jung, Taewon*, +, *T-ED May 84* 588–595
- Photovoltaic power cell metallization**
- contact resistance in solar cell; measurement and relative importance to power loss. *Meier, Daniel L.*, +, *T-ED May 84* 647–653
 - high-temperature-stable contact metallization for Si solar cells. *Lowe, Virginia E.*, +, *T-ED May 84* 626–629
 - overview of ohmic contacts on solar cells. *Schroder, Dieter K.*, +, *T-ED May 84* 637–647
 - thick-film screen-printing technology for Si solar cell metallization. *Cheek, Gary C.*, +, *T-ED May 84* 602–609

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Photovoltaic power cell radiation effects

dependence of spectral response of Si photovoltaic cells on optical illumination intensity. *Mbewe, Dominic Jacob, + , T-ED May 84 523–527*

equivalent electron fluence for proton irradiation in space qualification of shallow junction heteroface GaAs solar cells. *Wilson, John W., + , T-ED May 84 625*

light-induced junction modification in (Cd,Zn)S/CuInSe₂ solar cells. *Potter, Richard T., + , T-ED May 84 571–577*

MIS, SIS, N/P and MINP Si solar cells subjected to electron irradiation, long-term dark storage, and high-intensity UV irradiation. *Thuyer, M., + , T-ED May 84 619–621*

model for short-circuit current reduction caused by proton-induced damage in GaAs solar cells. *Wilson, John W., + , T-ED Apr 84 421–422*

photocapacitance and current collection in CdS/CdTe thin-film solar cells. *Isett, Lawrence C., T-ED May 84 664–670*

Photovoltaic power cell testing

equivalent electron fluence for proton irradiation in space qualification of shallow junction heteroface GaAs solar cells. *Wilson, John W., + , T-ED May 84 625*

Photovoltaic power cell thermal factors

high-temperature-stable contact metallization for Si solar cells. *Lowe, Virginia E., + , T-ED May 84 626–629*

Photovoltaic power cells

analysis of solar cells incorporating high – low junctions and operating between low- and high-level injection. *Wolf, Michael A., + , T-ED May 84 684–689*

current transport in Boeing (Cd,Zn)/CuInSe₂ solar cells. *Miller, Wesley A., + , T-ED May 84 654–661*

effect of areal inhomogeneities on minority-carrier MIS solar cell performance. *Roenker, Kenneth P., T-ED Dec 84 1838–1844*

flux enhancement and efficiency for photovoltaic cells. *Dixit, V., + , T-ED Dec 84 1901–1906*

influence of wavelength of incident light on shunt conductance and fill factor in amorphous Si solar cells. *Maruska, H. Paul, + , T-ED May 84 551–558*

light-bias effects on spectral current response and spectral capacitance characteristics of CdS/CuInSe₂ thin-film heterojunction solar cells. *Hegedus, Steven S., T-ED May 84 629–633*

limiting efficiency of Si solar cells. *Tiedje, Tom, + , T-ED May 84 711–716*

limits on open-circuit voltage and efficiency of Si solar cells imposed by intrinsic Auger processes. *Green, Martin A., T-ED May 84 671–678*

modeling of grain boundary effects on photovoltaic properties of metal-insulator thin-film polycrystalline semiconductor solar cells. *Sc, S. M., + , T-ED May 84 696–707*

optical absorption of thin films deposited on Lambertian reflector substrate. *Sheng, Ping, T-ED May 84 634–636*

optical confinement type a-Si:H solar cell using milky tin oxide on glass substrate. *Iida, H., + , T-ED May 84 718–719*

optically controlled amorphous Si photosensitive device. *Maruska, H. Paul, + , T-ED Sep 84 1343–1345*

photovoltaics (special issue). *T-ED May 84 522–721*

physics and modeling of heavily doped emitters. *del Alamo, Jesús A., + , T-ED Dec 84 1878–1888*

point-contact Si solar cells for high-concentration applications. *Swanson, Richard M., + , T-ED May 84 661–664*

polycrystalline thin-film CuInSe₂/CdZnS solar cells. *Mickelsen, Reid A., + , T-ED May 84 542–546*

recombination velocity of polysilicon grain boundaries; nonequilibrium behavior of depletion, inversion, and accumulation grain boundaries. *Böhm, Markus, + , T-ED Oct 84 1440–1446*

shallow junction heteroface n-p GaAs solar cells for space applications with AMO efficiency in 22.7–23.9% range. *Parekh, Rajul H., + , T-ED May 84 689–695*

Si solar cells with 18.7% efficiency. *Green, Martin A., + , T-ED May 84 679–683*

state-of-the-art review of high-efficiency GaAs solar cell development with emphasis on AlGaAs – GaAs cells for space applications. *Knechtli, Ronald C., + , T-ED May 84 577–588*

structurally stable thin Si solar cells. *Meulenberg, A., + , T-ED May 84 720–721*

surface-passivated Si solar cells with 17 – 18% efficiency. *Rohagi, Ajeeet, + , T-ED May 84 596–601*

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- transient capless annealing of ion-implanted GaAs. *Clarke, R. Chris, + , T-ED Aug 84* 1077–1082
- Semiconductor device thermal factors; cf. Integrated-circuit thermal factors; Photovoltaic power cell thermal factors; Second breakdown**
- Semiconductor devices**
- abstracts from 42nd (1984) Annual Device Research Conference (special section). *T-ED Dec 84* 1961–1988
- electron devices history (special Centennial issue). *T-ED Nov 84* 1521–1672
- MIS, SIS, N/P and MINP Si solar cells subjected to electron irradiation, long-term dark storage, and high-intensity UV irradiation. *Thayer, M., + , T-ED May 84* 619–621
- Semiconductor devices; cf. Amorphous semiconductor materials/devices; Bipolar transistors; Charge-coupled devices; FETs; Integrated circuits; Piezoelectric semiconductor materials/devices; Power semiconductor devices; Semiconductor diodes; Transistors**
- Semiconductor diode switches**
- static shielding diodes; low-loss high-speed p-n diode with channel structure to increase reverse blocking voltage. *Shimizu, Yoshiteru, + , T-ED Sep 84* 1314–1319
- Semiconductor diodes**
- bipolar-mode Schottky contacts; use to improve conventional Schottky diodes and p-n diodes. *Amemiya, Yoshihito, + , T-ED Jan 84* 35–42
- breakdown voltage optimization of Si p – π – ν planar junction diodes. *Hwang, Kyuwoon, + , T-ED Sep 84* 1126–1135
- correction to 'On the current – voltage characteristics of n⁺-p-p⁺ diodes' (Dec 83 1709–1716). *Chuang, C. T., T-ED Jun 84* 843
- deep levels at p-n and n-p AlGaAs – GaAs heterojunction interfaces. *Rys, Andrzej, + , T-ED Apr 84* 500–505
- negative differential resistance in quantum-state transfer superlattice diodes (Abstr.). *Kirchoefer, S. W., + , T-ED Dec 84* 1985
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- unifying view of transient responses for determining lifetime and surface recombination velocity in Si diodes and back-surface-field solar cells. *Jung, Taewon, + , T-ED May 84* 588–595
- Semiconductor diodes; cf. Avalanche diodes; Electroluminescent materials/devices; IMPATT diode ...; Millimeter-wave diodes; p-i-n diodes; Photodiodes; Point-contact diodes; Schottky-barrier diodes; Varactors**
- Semiconductor electronics industry; cf. Electronics industry**
- Semiconductor growth**
- (AlGa)As/GaAs double-heterostructure laser development. *Hayashi, Izuo, T-ED Nov 84* 1630–1642
- historical account of early Si crystal-growing experience at General Electric; growth of oxygen-free Si. *Thomas, Robert C., T-ED Nov 84* 1547–1549
- threshold voltage standard deviation for MESFETs on liquid-encapsulated Czochralski grown semi-insulating GaAs substrates. *Ishii, Yasunobu, + , T-ED Jun 84* 800–804
- Semiconductor growth; cf. Epitaxial growth**
- Semiconductor heterojunctions**
- staggered line-up (Al,In)As/InP heterojunctions as sources of tunable below-gap radiation; experimental verification (Abstr.). *Caine, E. J., + , T-ED Dec 84* 1984
- Semiconductor heterojunctions; cf. Gallium materials/devices**
- Semiconductor impurities; cf. Semiconductor device doping**
- Semiconductor – insulator interfaces**
- CCD-based technique for measuring interface trap density near band edges. *Madan, Sudhir K., + , T-ED Oct 84* 1509–1511
- charge-pumping measurements for determination of Si – SiO₂ interface state density directly on MOS transistors. *Groeseneken, Guido, + , T-ED Jan 84* 442–453
- influence of nonoxidizing Si – SiO₂ interface on excess interstitial distribution during thermal oxidation of Si. *Shin, Yun-Sheng, + , T-ED Jun 84* 797–800

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Semiconductor junctions

breakdown voltage of rectangular planar diffused junction with rounded corners. *Akhtar, J., + , T-ED Dec 84* 1781–1783
field and related semiconductor-surface and equilibrium-step-junction variables in terms of general solution. *Warner, R. M., Jr., + , T-ED Jul 84* 994–996

Semiconductor junctions; cf. Semiconductor heterojunctions**Semiconductor lasers**

electronic phenomena based on multilayer epitaxy. *Gossard, Arthur C., T-ED Nov 84* 1667–1672
single-quantum-well PbEuSeTe diode lasers; CW operation up to 174 K (at 4.41 μm) and pulsed operation up to 241 K (at 4.01 μm). *(Abstr.) Partin, D. L., T-ED Dec 84* 1975

Semiconductor logic circuits; cf. Bipolar integrated circuits; CMOS integrated circuits; FET integrated circuits; Logic arrays; VIOS integrated circuits; Schottky-barrier FET logic circuits; Very high-speed integrated circuits**Semiconductor materials; cf. Photovoltaic power cell materials****Semiconductor memories; cf. MNOS memories; MOS integrated circuits, memory****Semiconductor noise; cf. Semiconductor device noise****Semiconductor switches; cf. Bipolar transistor switches; FET switches; Power bipolar transistor switches; Power FET switches; Semiconductor diode switches; Thyristors****Sensitivity analysis/optimization**

sensitivity of SPICE simulations to input parameter variations. *Cassard, Janet M., T-ED Feb 84* 264–269

Sensors; cf. Transducers**Signal quantization; cf. Digital – analog conversion****Signal sampling/reconstruction; cf. Digital – analog conversion****Silicon materials/devices**

carrier lifetime as function of injection level in Au-doped Si. *Abbas, C. Christiaan, T-ED Oct 84* 1428–1432

conduction mechanism of silicon nitride films. *Liou, Fu-Tai, + , T-ED Dec 84* 1736–1741

electrical conduction model for polycrystalline Si; role of grain boundaries. *Joshi, Dinesh Prasad, + , T-ED Jul 84* 920–927

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theory of conduction in polysilicon; general I – V theory. *Khondker, A. N., + , T-ED Apr 84* 493–500

theory of conduction in polysilicon; small-signal theory. *Kim, Dae M., + , T-ED Apr 84* 480–493

Silicon materials/devices; cf. Specific topic**Silicon-on-insulator circuits**

FIPOS (full isolation by porous oxidized silicon) technology and its application to LSI. *Inai, Kazuo, + , T-ED Mar 84* 297–302

heat source and temperature profile in silicon-on-insulator multi-layer structure illuminated by incoherent light source. *Kyung, Chong Min, T-ED Dec 84* 1845–1851

hydrogenation by ion implantation for VLSI/SOI applications; SOI/PMOS transistors for use in static RAMs (Abstr.). *Singi, H. J., + , T-ED Dec 84* 1981–1982

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Silicon-on-insulator devices

charge-based large-signal model for thin-film SOI MOSFETs (Abstr.). *Lim, H. K., + , T-ED Dec 84* 1983

current – voltage characteristics of thin-film silicon-on-insulator MOSFETs. *Lim, Hyung-Kyu, + , T-ED Apr 84* 401–408

mathematical modeling of semiconductor-on-insulator device operation. *Yamaguchi, Ken, T-ED Jul 84* 977–982

MOSFETs fabricated in laser-recrystallized Si on quartz using selectively absorbing dielectric layers. *Possin, George E., + , T-ED Jan 84* 68–74

Simulation; cf. Specific topic**Solar cells; cf. Photovoltaic power cells****Solid lasers; cf. Semiconductor lasers****Space charge**

field and related semiconductor-surface and equilibrium-step-junction variables in terms of general solution. *Warner, R. M., Jr., + , T-ED Jul 84* 994–996

lasing in fast-wave devices due to ac space-charge effects. *Döhler, G., T-ED Mar 84* 386–389

Special issues/sections

abstracts from 42nd (1984) Annual Device Research Conference (special section). *T-ED Dec 84* 1961–1988

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III-V compound semiconductor processing. *T-ED Aug 84* 1013–1103

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photovoltaics. *T-ED May 84* 522–721

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Spheres

temperature measurement of coated-particle cathode of spherical geometry using retarding field method. *Dallos, Andras, + , T-ED Mar 84* 379–381

Strip transmission lines; cf. Microstrip**Strip waveguides; cf. Optical strip waveguides****Submillimeter-wave diodes; cf. Submillimeter-wave mixers****Submillimeter-wave mixers**

formation of planar n⁺ pockets in GaAs for mixer diode fabrication. *Griffin, James A., + , T-ED Aug 84* 1096–1099

Submillimeter-wave (300 – 3000 GHz); cf. Millimeter-wave (30 – 300 GHz)**Superconducting devices; cf. Josephson devices****Superconducting quantum interference devices; cf. Josephson devices****Surface discharges**

influence of surface charge and bevel angle on blocking behavior of high-voltage p+n-n+ device. *Brieger, K.-P., + , T-ED Jun 84* 733–738

Surfaces; cf. Specific topic**Switched-capacitor filters**

micropower monolithic filters realized using bipolar-compatible JFET technology; switched-capacitor and continuous analog filters. *Parpia, Zahir, + , T-ED Feb 84* 165–171

Switches/switching; cf. Light-triggered switches; Semiconductor diode switches**Switching systems; cf. Communication switching****Symbols**

symbolic design methodology for three-dimensional CMOS circuits. *Hoeflinger, Bernd, + , T-ED Feb 84* 171–173

T

Technological innovation

path to conception of junction transistor. *Shockley, William, T-ED Nov 84* 1523–1546

Technology forecasting

future of ultra-large scale integration based on theoretical, practical, and analogical limits. *Meindl, James D., T-ED Nov 84* 1555–1561

Tellurium materials/devices; cf. Specific topic**Temperature measurement**

temperature measurement of coated-particle cathode of spherical geometry using retarding field method. *Dallos, Andras, + , T-ED Mar 84* 379–381

Testing; cf. Integrated-circuit testing**Thermal factors; cf. Integrated-circuit thermal factors; Laser thermal factors; Semiconductor device noise; Semiconductor device thermal factors****Thermal image sensors; cf. Infrared image sensors****Thermal variables measurement; cf. Temperature measurement****Thermionic emission; cf. Electron emission****Thick-film device fabrication**

thick-film screen-printing technology for Si solar cell metallization. *Cheek, Gary C., + , T-ED May 84* 602–609

Thin-film devices; cf. Specific topic**Thin-film transistors**

depletion PMOS transistors in passivated polysilicon films; effects of Si₃N₄ and Al films on passivation (Abstr.). *Rodder, M., + , T-ED Dec 84* 1982–1983

history of thin-film transistors; development and use in TFT-addressed displays. *Brody, T. Peter, T-ED Nov 84* 1614–1628

Thyatron

thyatron operation using He for high-power high-repetition rate applications; use with excimer lasers. *Guha, Shekhar, + , T-ED Jul 84* 992–993

Thyristors

electrothermally failure-safe double-interdigitated GTO thyristor. *Silard, Andrei P., + , T-ED Mar 84* 322–328

gated V-groove p-i-n diode static induction thyristor. *Fisher, Carole A., + , T-ED Sep 84* 1299–1308

GTO thyristor turn-off failure mechanism. *Nakagawa, Akio, + , T-ED Mar 84* 273–279

high-temperature physical effects underlying failure mechanism in thyristors under surge conditions. *Silard, Andrei P., T-ED Sep 84* 1334–1340

influence of surface charge and bevel angle on blocking behavior of high-voltage p+n-n+ device. *Brieger, K.-P., + , T-ED Jun 84* 733–738

model for GTO thyristor during switch-off. *Gough, Paul A., + , T-ED Dec 84* 1796–1803

time-dependent and temperature-dependent 2-D simulation of GTO thyristor turn-off process. *Nakagawa, Akio, + , T-ED Sep 84* 1156–1163

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- turn-off, turn-on and high-frequency switching characteristics of 45-A 1500-V double-interdigitated GTO switches. *Silard, Andrei P., T-ED Sep 84* 1230–1237
- ultrahigh-voltage high-current gate turn-off thyristors. *Yatsuo, Tsutomu, +, T-ED Dec 84* 1681–1686
- Transducers;** cf. Chemical transducers; Magnetic transducers; Optical transducers
- Transferred-electron devices;** cf. Gunn devices
- Transistors**
- charge-injection transistor based on real-space hot-electron transfer. *Luryi, Serge, +, T-ED Jun 84* 832–839
- Transistors;** cf. Bipolar transistors; CMOSFETs; FETs; JFETs; Microwave bipolar transistors; Microwave FETs; Millimeter-wave bipolar transistors; Millimeter-wave FETs; Permeable base transistors; Phototransistors; Power bipolar transistors; Power FETs; Schottky-barrier FETs; Thin-film transistors
- Trapping;** cf. Charge-carrier processes
- Traveling-wave amplifiers**
- capacitively coupled traveling-wave amplifier with improved power-handling capability. *Ayasli, Yalcin, +, T-ED Dec 84* 1937–1942
 - input/output coupling in reflection-type tapered gyrotron traveling-wave amplifier. *Lau, Y. Y., +, T-ED Mar 84* 337 (347)
- Traveling-wave tubes**
- large-signal theory of two-stage tapered gyro-TWT. *Ganguly, Achintya K., +, T-ED Apr 84* 474–480
- Tunable lasers;** cf. Laser tuning
- Tuned amplifiers**
- charge-control analysis of class E switching-mode tuned power amplifier with only one inductor and one capacitor in load network. *Kazimierczuk, Marian, T-ED Mar 84* 366–373
- Tunnel effect**
- calculation of tunneling current in ion-implanted (Hg,Cd)Te photodiodes using two-sided junction potential. *Beck, William A., +, T-ED Mar 84* 292–297
 - current transport in Boeing (Cd,Zn)/CuInSe₂ solar cells. *Miller, Wesley A., +, T-ED May 84* 654–661
 - effect of graded layers and tunneling on performance of AlGaAs/GaAs heterojunction bipolar transistors. *Grinberg, Anatoly A., +, T-ED Dec 84* 1758–1765
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 - modification of characteristics of metal–semiconductor contacts by insertion of ultrathin amorphous Si layer at junction interface (Abstr.). *Yang, E. S., +, T-ED Dec 84* 1981
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- TV cameras; cf. TV image sensors**
- TV image sensors**
- CCD color signal separation IC for single-chip color imagers with color filter arrays. *Watanabe, Takashi, +, T-ED Feb 84* 183–188
- TWT;** cf. Traveling-wave tubes
- U**
- Ultraviolet radiation effects**
- MIS, SIS, N/P and MNIP Si solar cells subjected to electron irradiation, long-term dark storage, and high-intensity UV irradiation. *Thayer, M., +, T-ED May 84* 619–621
 - reciprocity behavior of photoresists in excimer laser lithography. *Rice, Sondra, +, T-ED Jan 84* 1–3
- V**
- Vacuum systems**
- photodiode quantum efficiency improvement and spectral response alteration through surface effects in vacuum. *Kopeika, N. S., +, T-ED Sep 84* 1198–1206
- Varactors**
- effects of transient carrier transport in millimeter-wave GaAs diodes. *Grondin, R. O., +, T-ED Jan 84* 21–28
- Very high-speed integrated circuits**
- analysis of crosstalk in very-high-speed LSI/VLSI using multiconductor MIS microstrip line model. *Seki, Shouhei, +, T-ED Dec 84* 1498–1953
 - analysis of interconnection delay on very-high-speed LSI/VLSI chips using MIS microstrip line model. *Hasegawa, Hideki, +, T-ED Dec 84* 1954–1960
 - coupling effects in time domain for interconnecting bus in high-speed GaAs logic circuits. *Chilo, Jean, +, T-ED Mar 84* 347–352
 - selectively doped heterostructure transistors for ultrahigh-speed integrated circuits (Abstr.). *Pei, S. S., +, T-ED Dec 84* 1962
 - test structures for propagation delay measurements on high-speed integrated circuits. *Long, Stephen I., T-ED Aug 84* 1072–1076
- Very large-scale integration**
- electrical performance and physics of isolation region structures for VLSI. *Goodwin, Scott H., +, T-ED Jul 84* 861–872
 - future of ultra-large scale integration based on theoretical, practical, and analogical limits. *Meindl, James D., T-ED Nov 84* 1555–1561
- Very large-scale integration; cf. Specific topic**
- VHF devices**
- vertical power MOSFET with self-aligned terraced gate which reduces parasitic gate capacitances. *Ueda, Daisuke, +, T-ED Apr 84* 416–420
- VHSIC;** cf. Very high-speed integrated circuits
- VLSI;** cf. Very large-scale integration
- Z**
- Zinc materials/devices; cf. Specific topic**

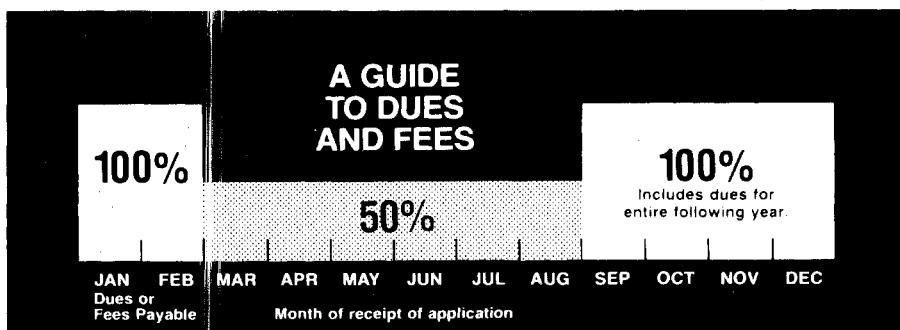
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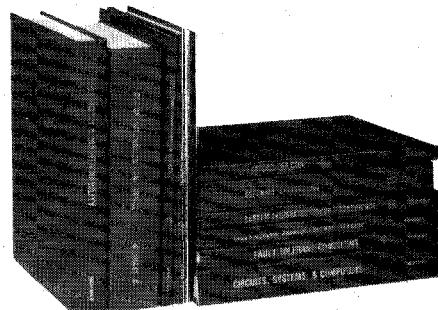
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Extension of the Scharfetter-Gummel Algorithm to the Energy Balance Equation	T. Tang	1912
Geometry Dependence of Dark Current in CCD's	J. Y. Chen and C. R. Viswanathan	1914
Anomalous MOS Capacitance Behavior in Depletion-Mode Structures	R. C. Jaeger and F. H. Gaensslen	1916
Temperature Dependence of Peak Drift Velocity and Threshold Field in n-In _{0.53} Ga _{0.47} As	A. Bhattacharyya, A. Ghosal, and D. Chattopadhyay	1918
Erratum	D. L. Carter	1919

SPECIAL ISSUE PAPERS

FOREWORD	W. R. Wisseman	1920
----------	----------------	------

Si Monolithic Microwave Prescaler IC	S. Watanabe, S. Shinozaki, N. Kusama, S.-I. Miyazaki, and T.-A. Nakata	1921
A 2-18-GHz Monolithic Distributed Amplifier Using Dual-Gate GaAs FET's	W. Kennan, T. Andrade, and C. C. Huang	1926
A Monolithic Direct-Coupled GaAs IC Amplifier with 12-GHz Bandwidth	S. B. Moghe, H.-J. Sun, T. Andrade, C. C. Huang, and R. Goyal	1931
Capacitively Coupled Traveling-Wave Power Amplifier	Y. Ayasli, S. W. Miller, R. Mozzl, and L. K. Hanes	1937
Wide-Band Monolithic Phase Shifter	Y. Ayasli, S. W. Miller, R. L. Mozzl, and L. K. Hanes	1943
Analysis of Crosstalk in Very High-Speed LSI/VLSI's Using a Coupled Multiconductor MIS Microstrip Line Model	S. Seki and H. Hasegawa	1948
Analysis of Interconnection Delay on Very High-Speed LSI/VLSI Chips Using an MIS Microstrip Line Model	H. Hasegawa and S. Seki	1954

42ND ANNUAL DEVICE RESEARCH CONFERENCE (ABSTRACTS)	1961
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1984 INDEX	Follows page	1988
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